

# Development of Large Area Fast Microchannel Plate Photodetectors

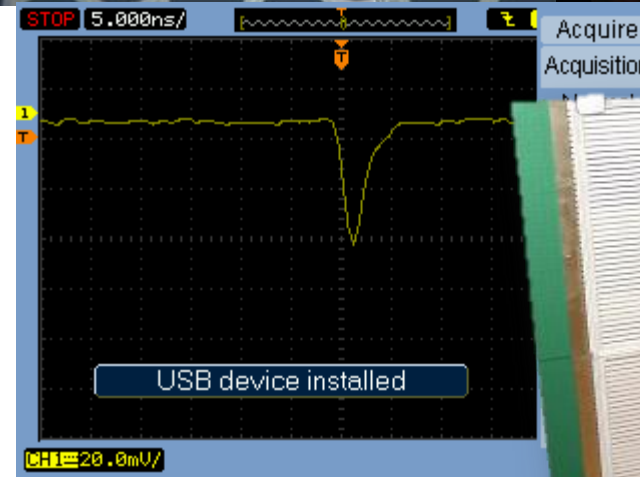
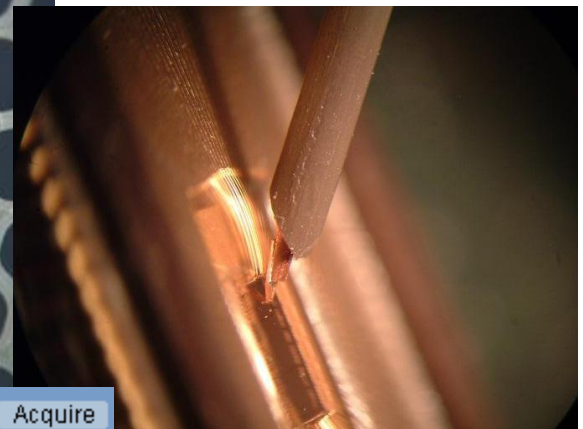
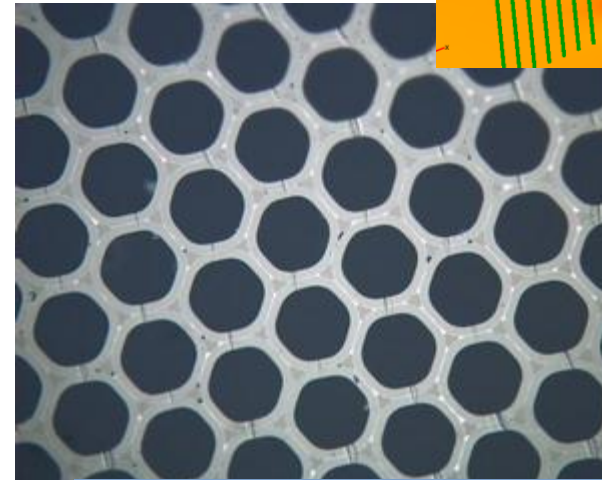
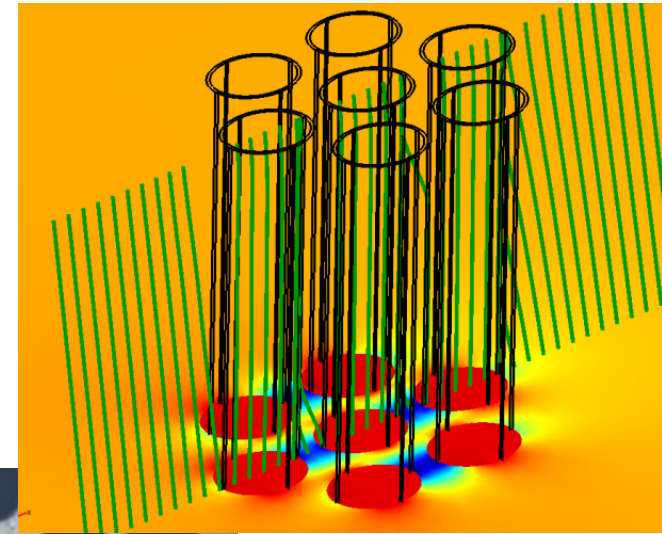
Karen Byrum

for the **L**arge **A**rea **P**icosecond **P**hoto**D**etector (LAPPD) Collaboration  
Argonne National Laboratory

SPIE Defense, Security and Sensing 2011  
Orlando Florida  
28 April 2011

# Talk Outline

- Introduction and Overview
- MCP Development
- Photocathodes
- Anode and signal readout
- Mechanical Design
- Simulations and Testing
- Conclusion



# Introduction: The LAPPD Collaboration

## Large Area Picsecond Photodetector Collaboration

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*Fermi National Accelerator Laboratory, Batavia, IL*

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Robert Abrams, valentin Ivanov, Thomas Roberts

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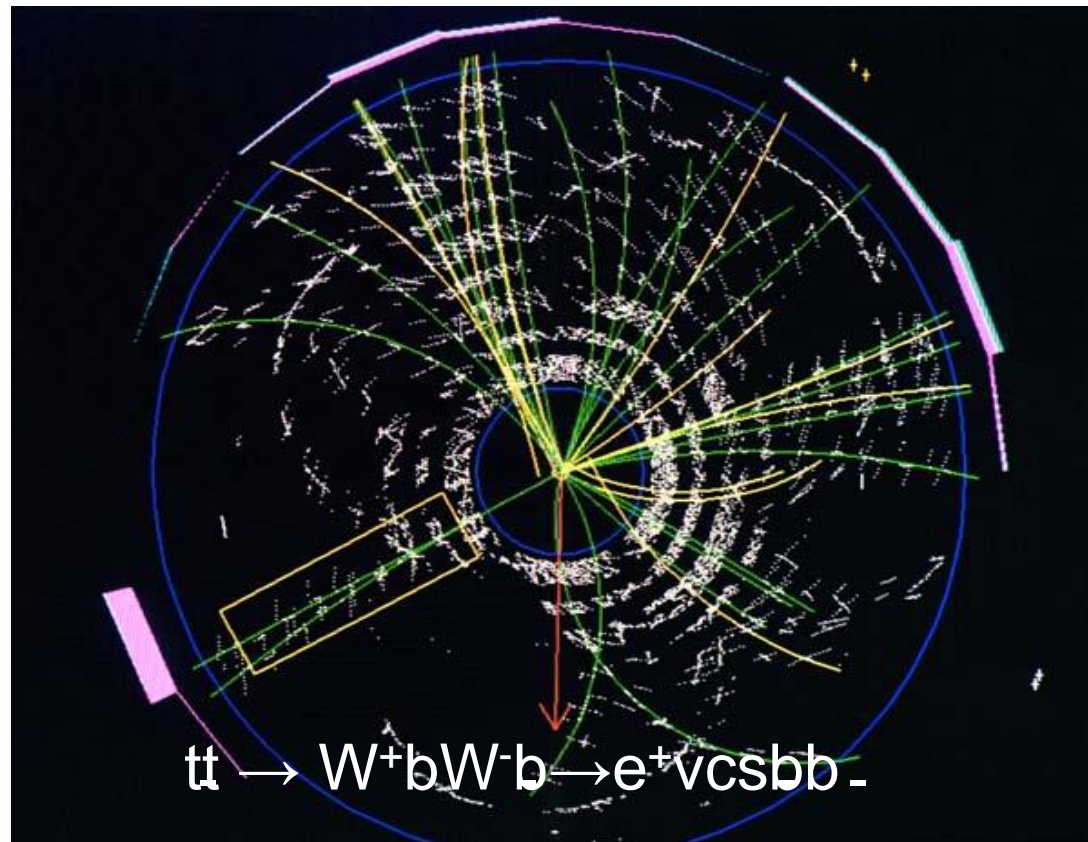
- Newly funded (end of August 2009) by DOE and NSF
- 4 National Labs
- 5 Divisions at Argonne
- 3 US small companies;
- Electronics expertise at Universities of Chicago and Hawaii
- Photocathode expertise at Washington University, St. Louis and Univ. of Illinois, Chicago

## Goals:

- Exploit advances in material science and nanotechnology to develop new, batch methods for producing cheap, large area MCPs.
- Develop path to a commercializable product on a three year time scale (approaching the end of .year 2 – this summer)

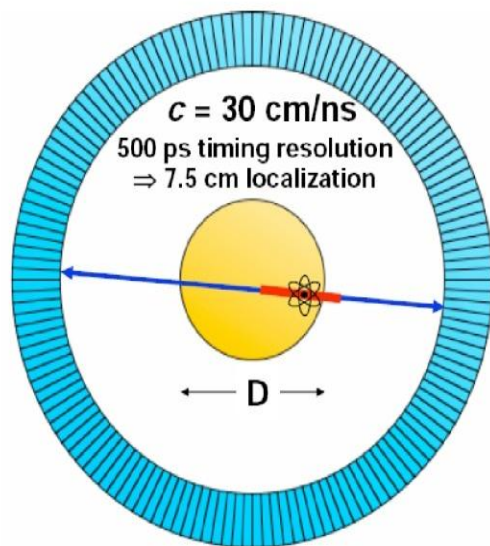


# Overview: Motivation



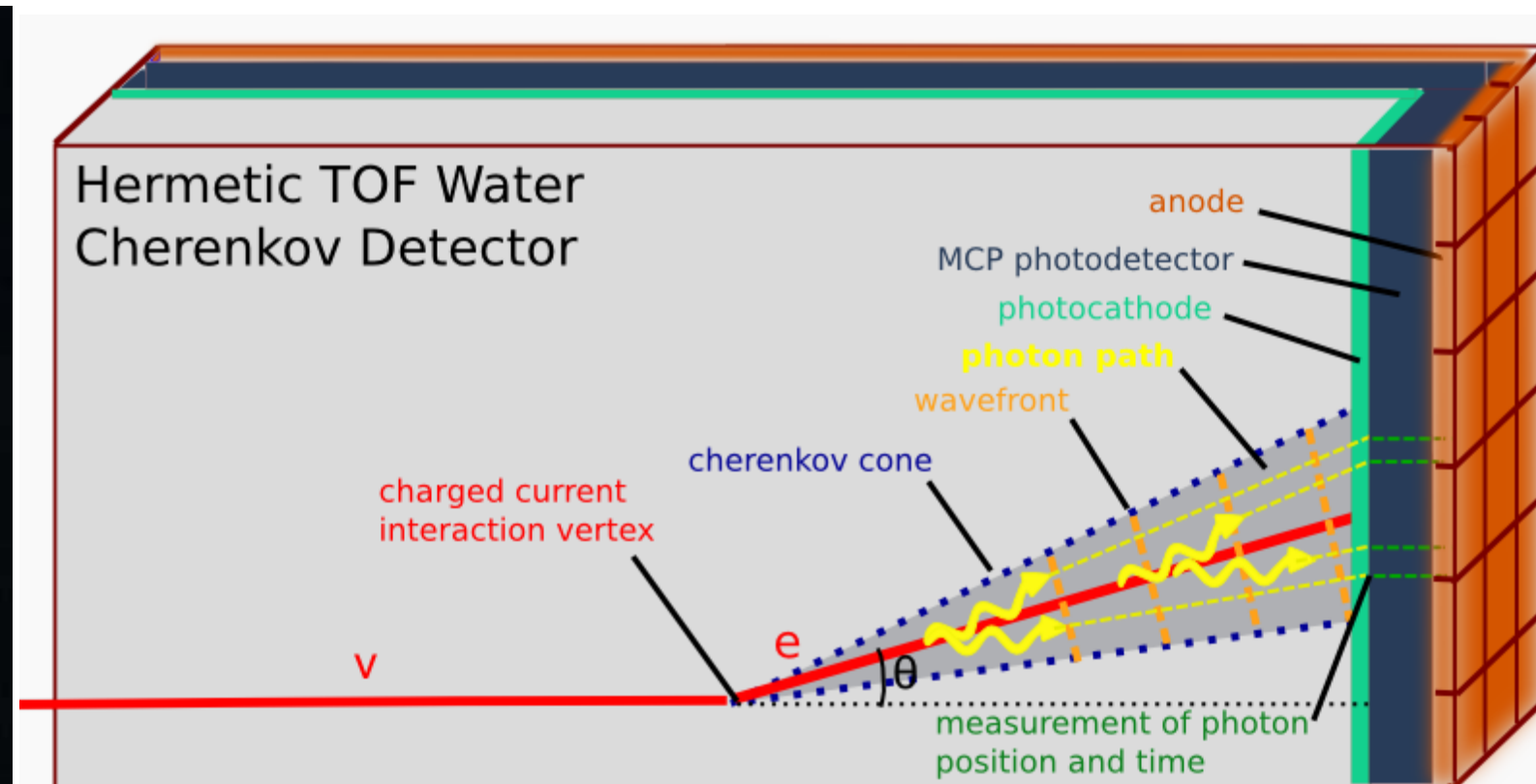
Complete particle measurement: E, p + **m(PID)**  
 1ps time & 1mm space resolution, \$100k/m<sup>2</sup>

## Time-of-Flight in PET



- Can localize source along line of flight.
- Time of flight information reduces **noise** in images.
- Variance reduction given by  $2D/c\Delta t$ .
- 500 ps timing resolution  
 $\Rightarrow$  5x reduction in variance!

• Time of Flight Provides a *Huge* Performance Increase!



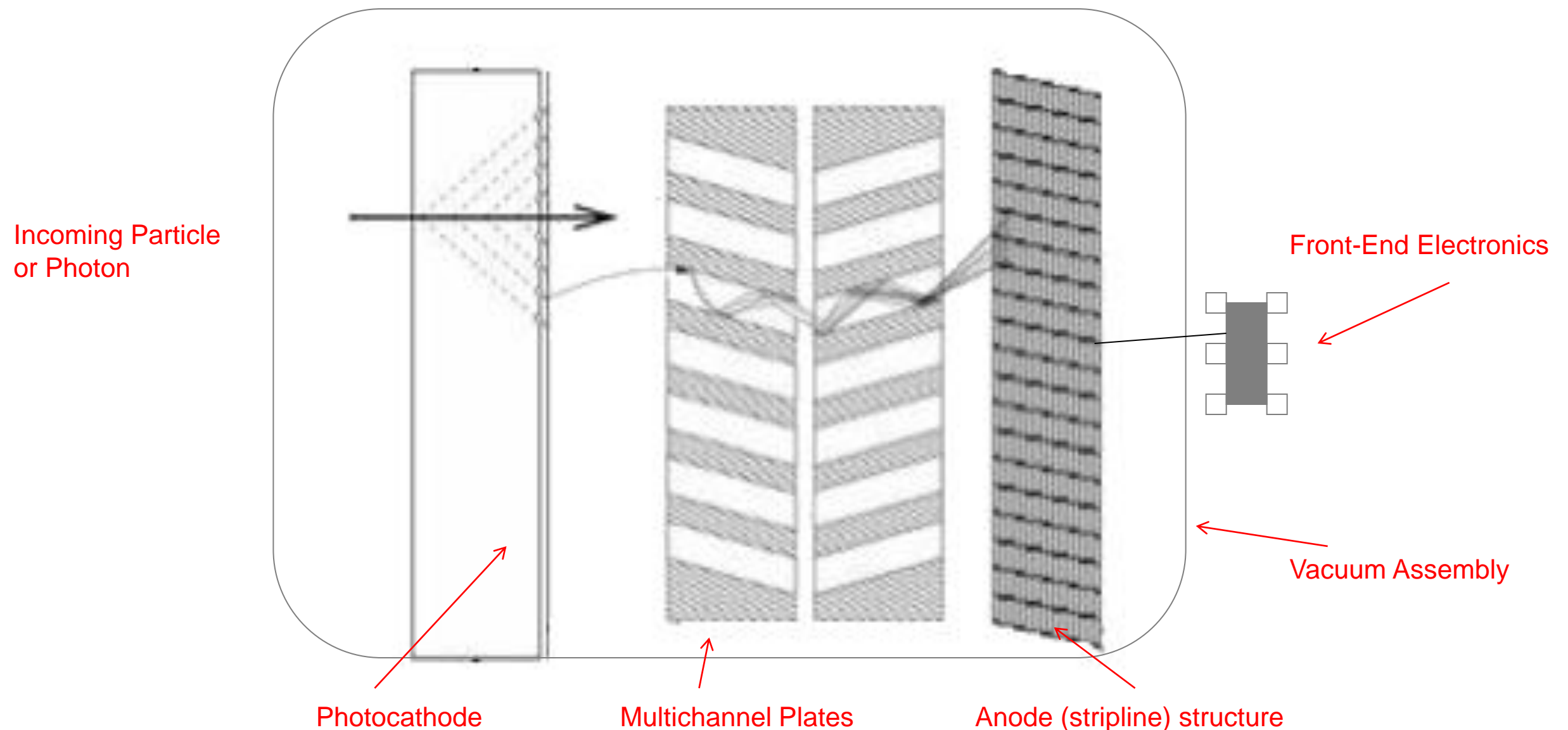
Water Cherenkov neutrino detector (DUSEL) ~80-90% coverage and 3-d photon vertex reconstruction  
 100ps time & 10mm space resolution, \$10k/m<sup>2</sup>

## TOF (Effective Efficiency) Gain for Whole-Body PET (35 cm)

Hardware	$\Delta t$ (ps)	TOF Gain
BGO Block Detector	3000	0.8
LSO Block (non-TOF)	1400	1.7
LSO Block (TOF)	550	4.2
LaBr <sub>3</sub> Block	350	6.7
LSO Side Coupled	250	9.3
LSO Small Crystal	210	11.1
LuI <sub>3</sub> Small Crystal	125	18.7
LaBr <sub>3</sub> Small Crystal	70	33.3

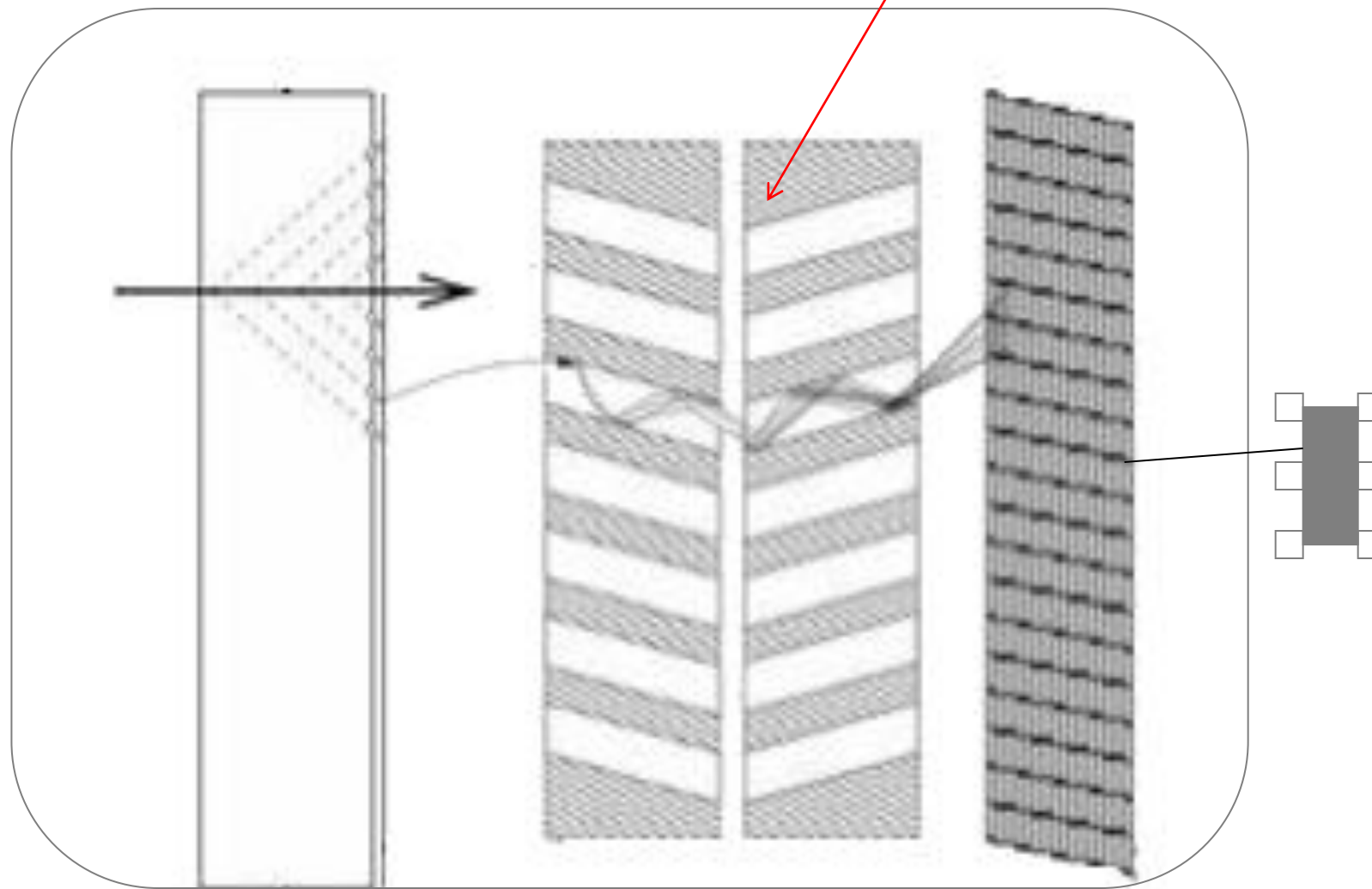
- **Incredible Gains Predicted**
- **Nothing Else Can Give Us Gains of This Size!**

# Overview: Micro Channel Plates PMTs



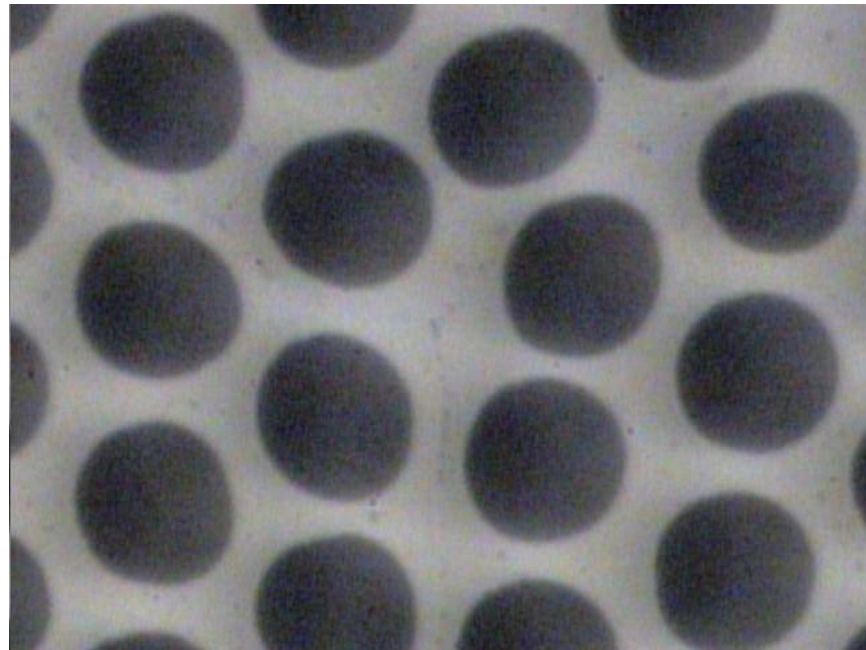
Photon and electron paths are short - few mm to microns which results in fast, uniform Planar geometry, scalable to large areas

# MCP Development Multichannel Plates

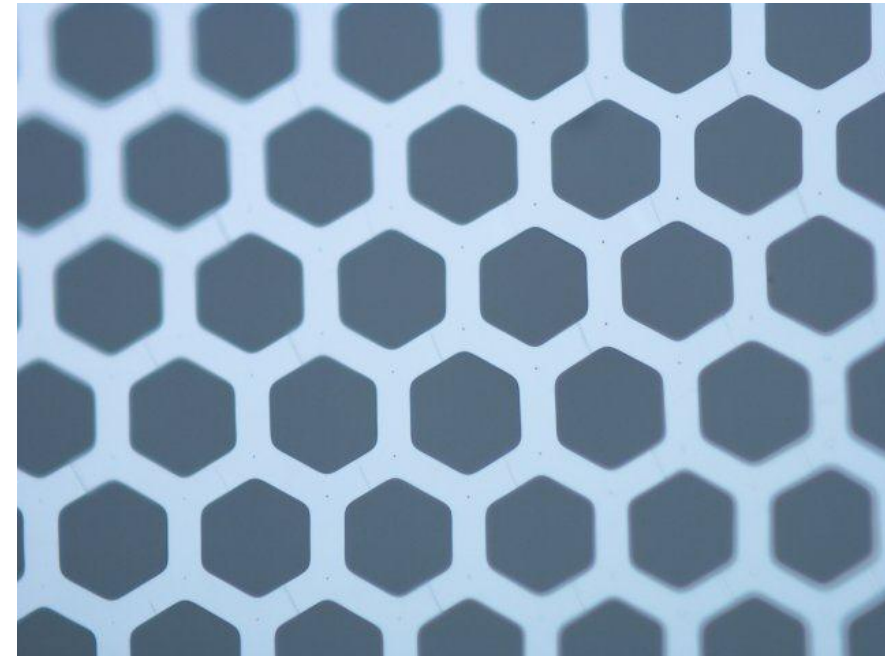




# MCP Development: Simplifying MCP Construction



**Conventional Pb-glass MCP**



**Incom Glass Substrate**

**Chemically produced and treated**

- Pb-glass provides 3 functions:
  - Provides pores
  - Resistive layer supplies electric field in the pore
  - Pb-oxide layer provides secondary electron emission

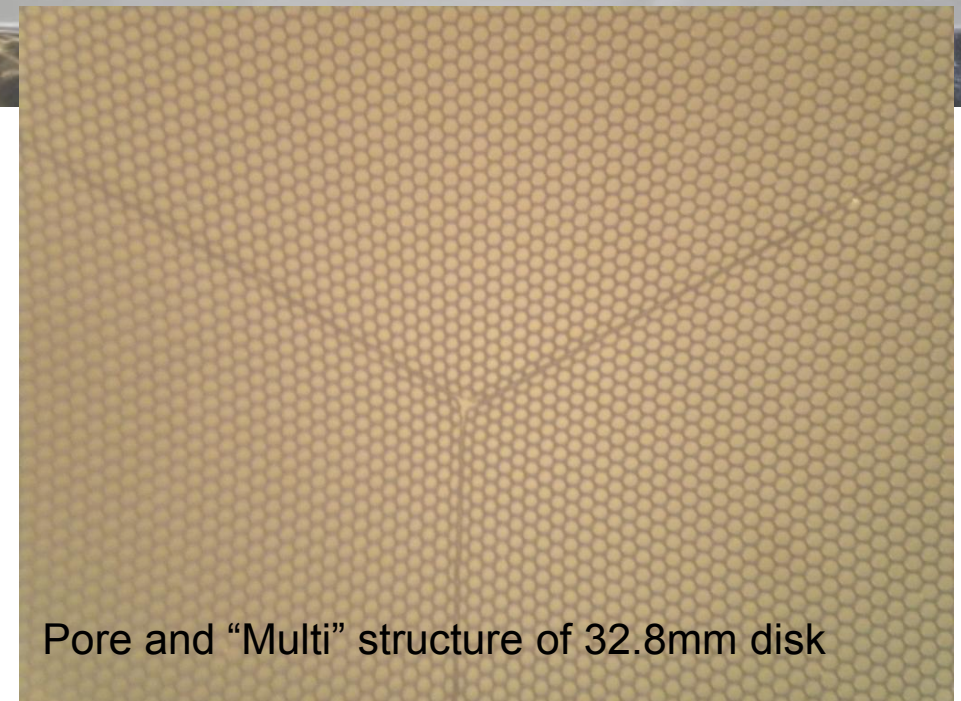
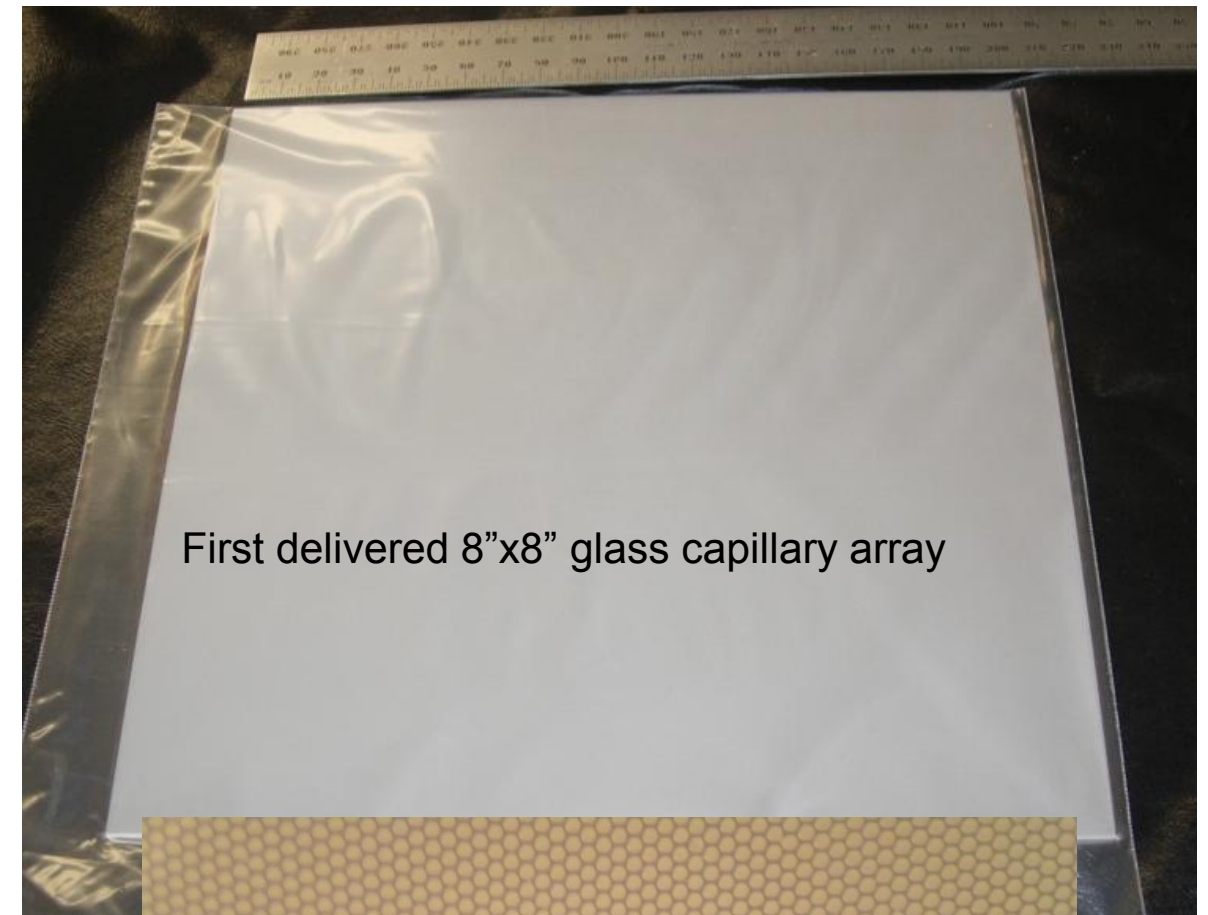
**Separate the three functions:**

- Hard glass substrate provides pores
- Separate Resistive and Emissive layer functions
- Produce Tuned Resistive Layer (Atomic Layer Deposition, ALD) provides current for electric field;
- Specific Emitting layer provides secondary electron emission

# MCP Development: Glass Capillary Substrate Development

## Incom

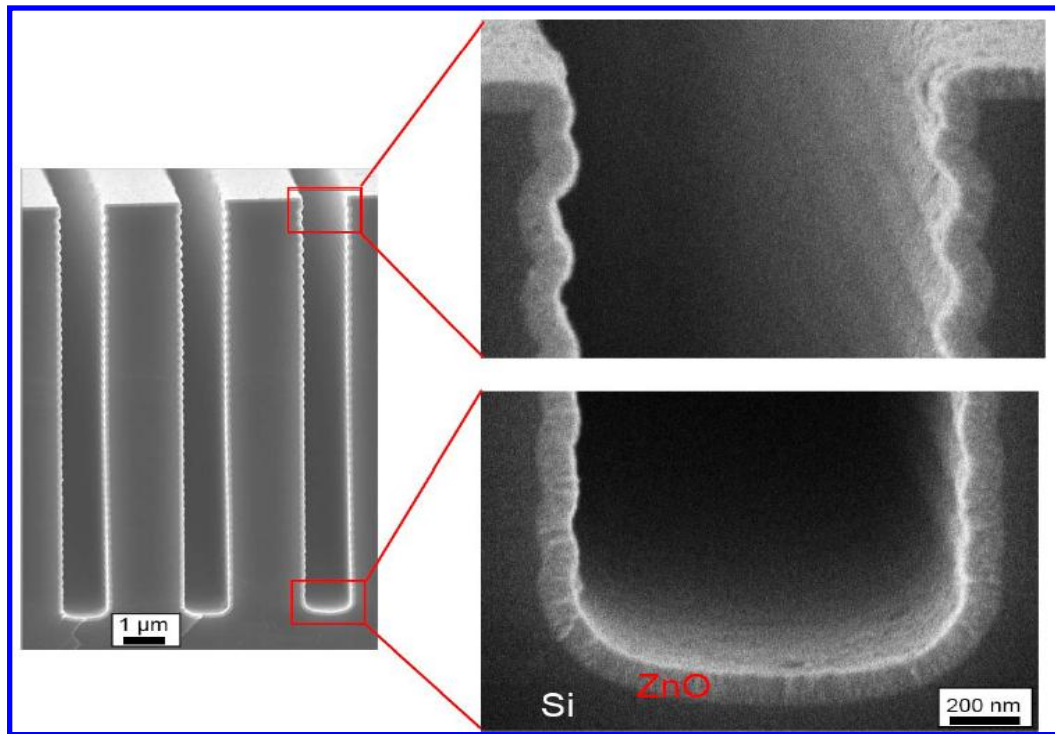
- Glass substrate development, fabrication, finishing by Incom, Inc. (Charlton, MA, USA)
  - Borosilicate glass capillary
- Disk development substrates produced in quantity (for R&D)
  - 32.8mm diameter
  - 20 $\mu$ m pore L/D=60
- All substrate pores have 8° bias w.r.t axis  $\perp$  to substrate
  - Used in pair chevron configuration to reduce positive ion feedback damage to photocathode
- **First four 8"x8" 20 $\mu$ m pore substrates delivered Aug 2010**





# MCP Development: Atomic Layer Deposition

Argonne, Arradiance



## ALD Thin Film Materials

H																	He				
Li	Be											B	C	N	O	F	Ne				
Na	Mg											Al	Si	P	S	Cl	Ar				
K	Ca	Sc	Ti	V	Cr	Mn	Fe	Co	Ni	Cu	Zn	Ga	Ge	As	Se	Br	Kr				
Rb	Sr	Y	Zr	Nb	Mo	Tc	Ru	Rh	Pd	Ag	Cd	In	Sn	Sb	Te	I	Xe				
Cs	Ba	La	Hf	Ta	W	Re	Os	Ir	Pt	Au	Hg	Tl	Pb	Bi	Po	At	Rn				
Fr	Ra	Lr	Rf	Db	Sg	Bh	Hs	Mt													
			Ce	Pr	Nd	Pm	Sm	Eu	Gd	Tb	Dy	Ho	Er	Tm	Yb	Lu					
			Th	Pa	U	Np	Pu	Am	Cm	Bk	Cf	Es	Fm	Md	No	Lw					

- Oxide
- Nitride
- Phosphide/Arsenide
- Sulphide/Selenide/Telluride
- Element
- Carbide
- Fluoride
- Dopant
- Mixed Oxide

- A conformal, self-limiting process.
- Allows atomic level thickness control.
- Applicable for a large variety of materials.

J. Elam, A. Mane, Q. Peng, T. Prolier (ANL:ESD/HEP),  
N. Sullivan (Arradiance), A. Tremsin (Arradiance, SSL)

Poster by Anil Mane on ALD and LAPPD project: Thur Conf. 8031

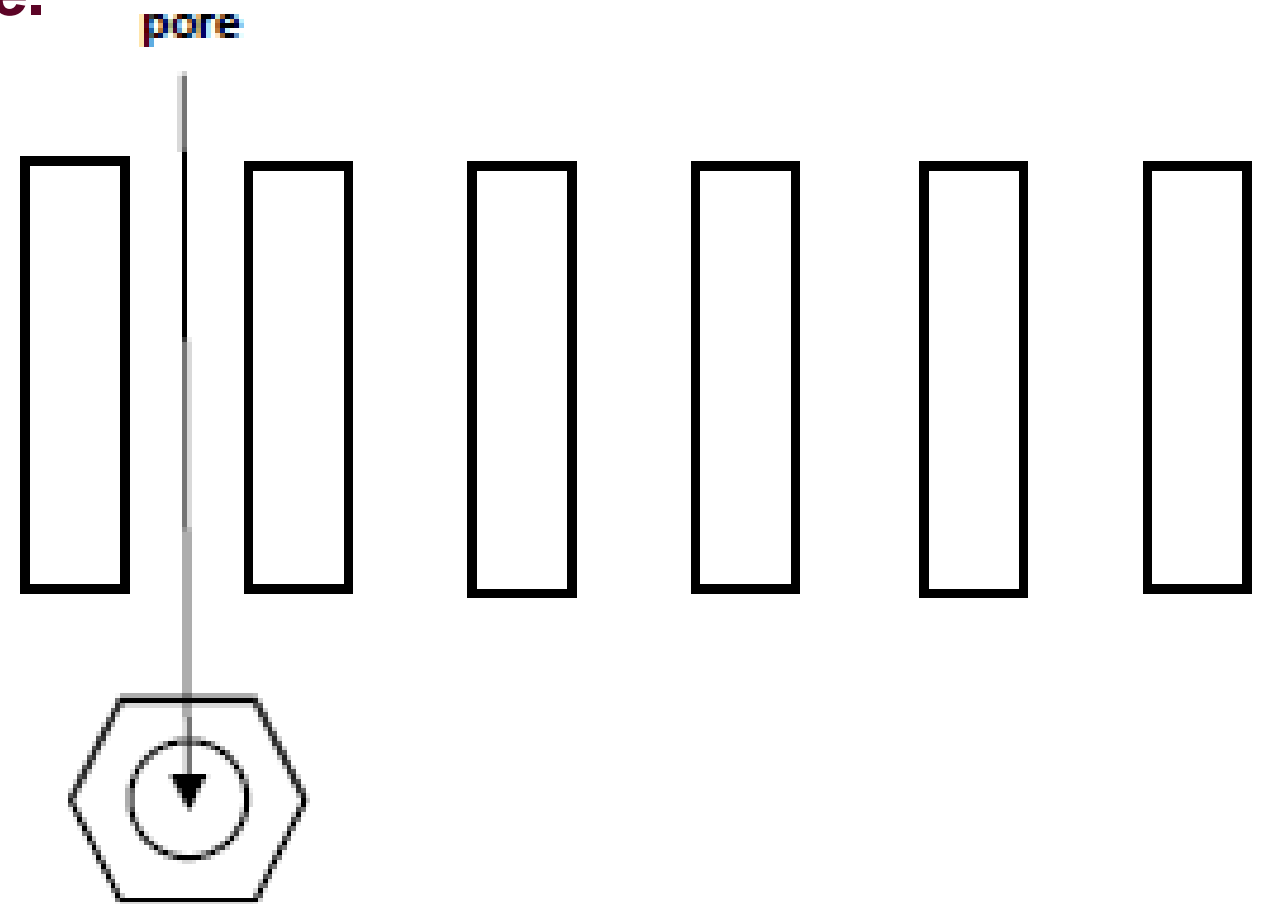
# MCP R&D : Channel Plate Fabrication w/ ALD

1. Start with a porous, insulating substrate that has appropriate channel structure.

Incom



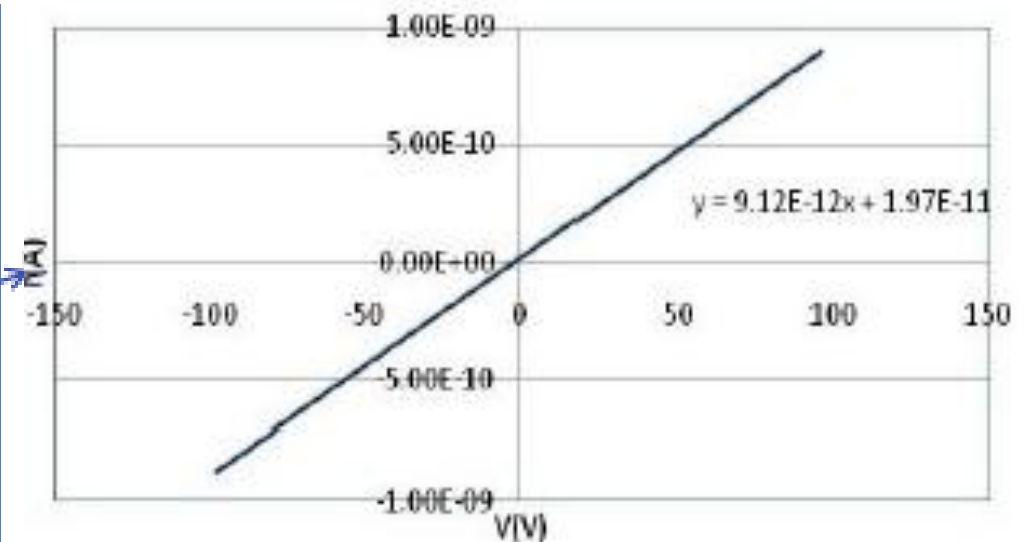
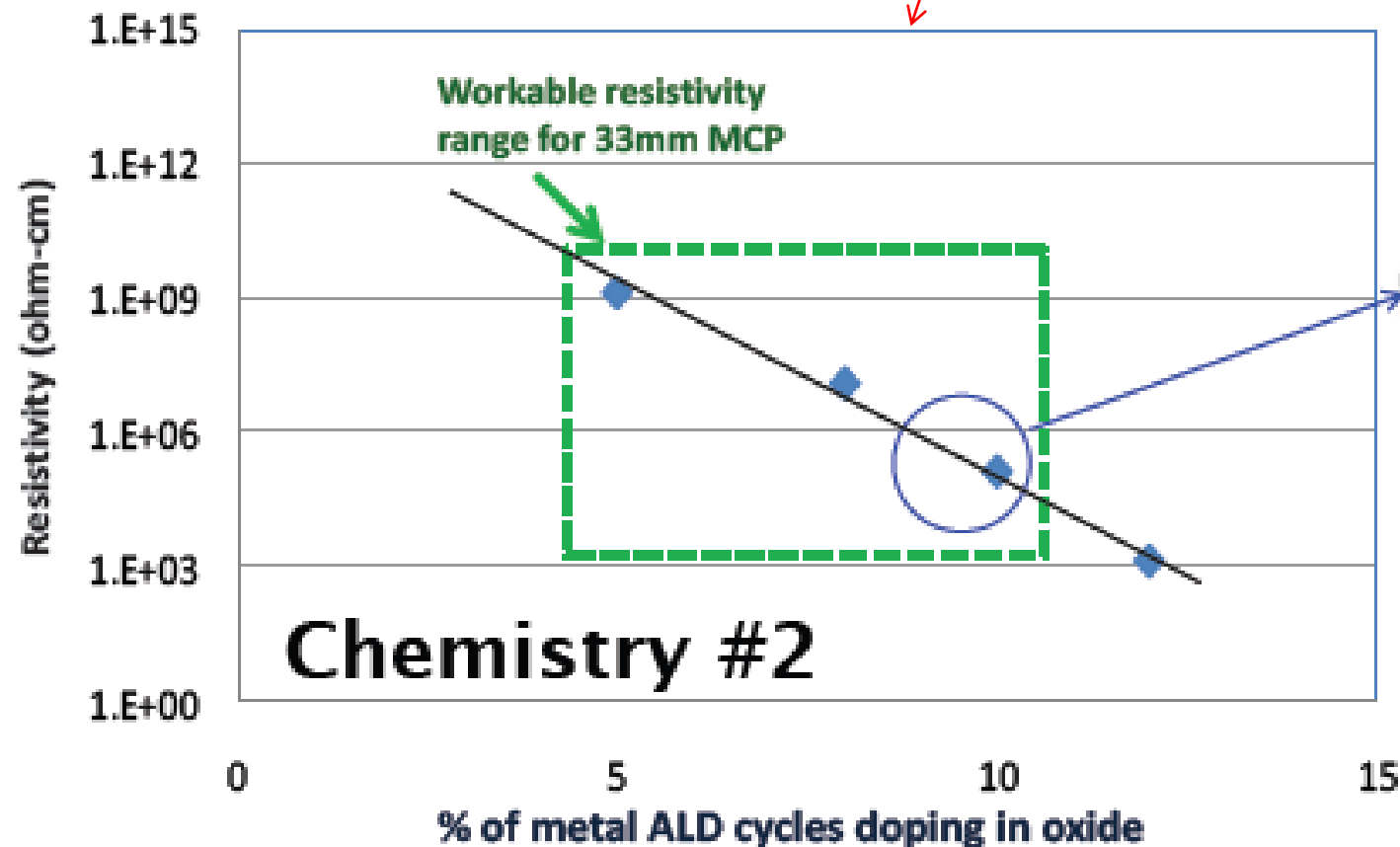
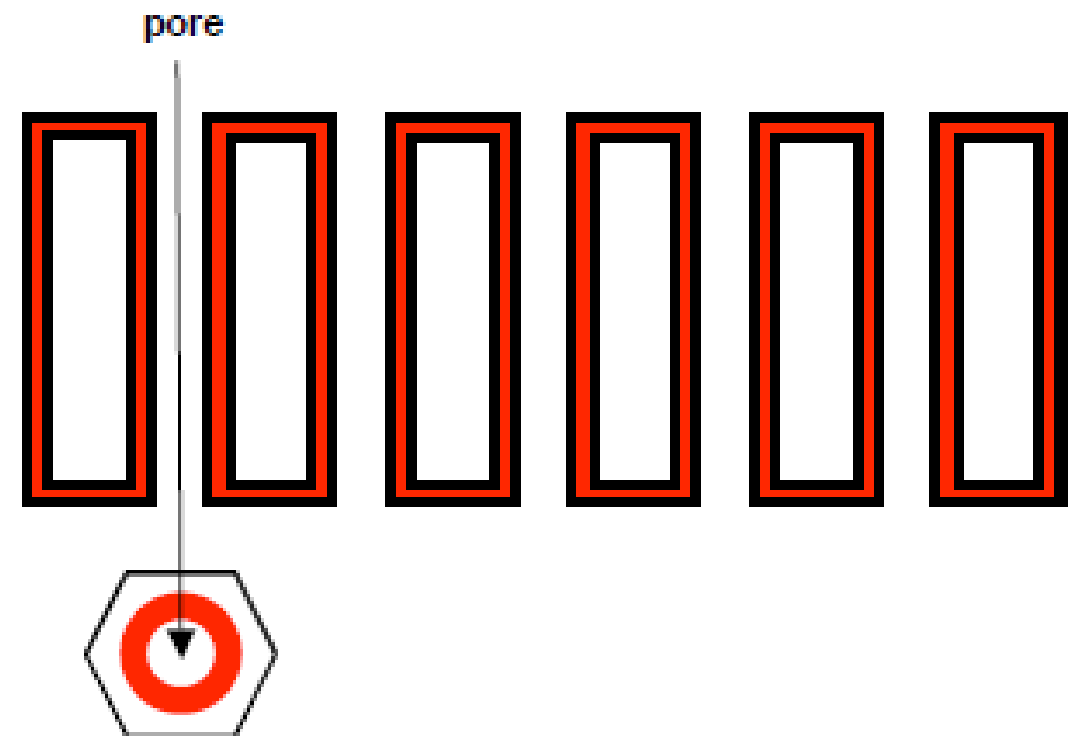
borosilicate glass filters



# MCP R&D : Channel Plate Fabrication w/ ALD

## 2. Apply a resistive coating (ALD)

- Good control of resistivity
- Uniform, smooth coating w/no etching
- Functionalized pair exhibited high gain
- Scalable to large surface



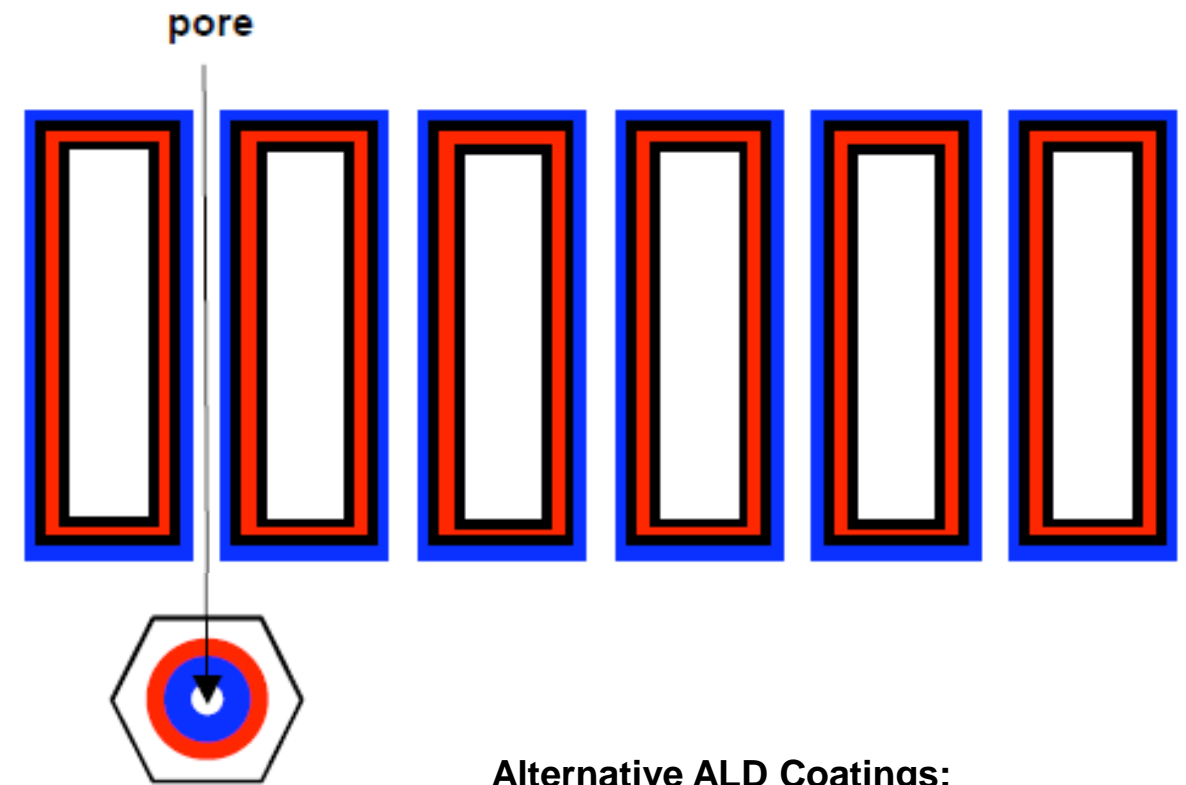
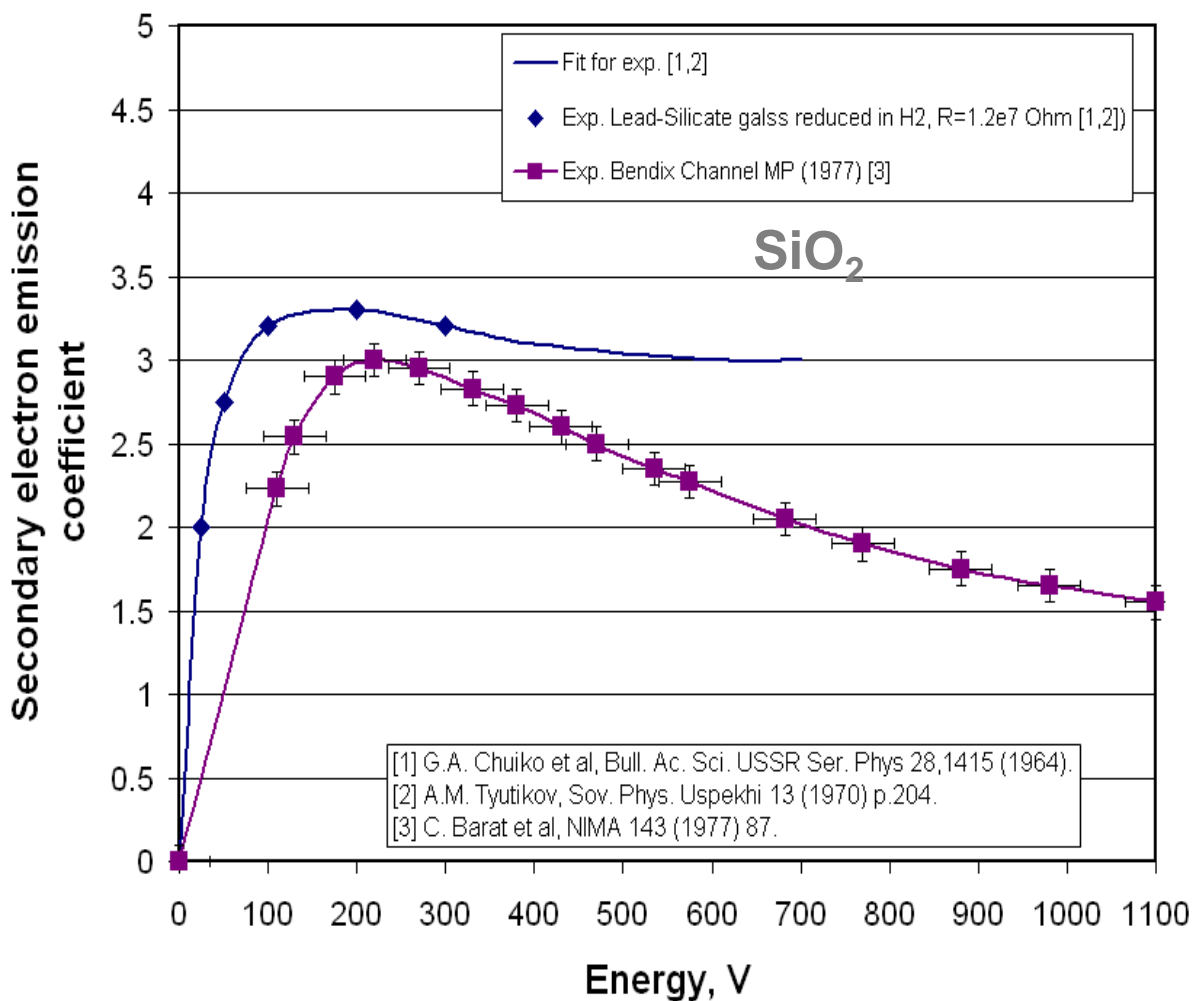
• Linear I-V on Glass



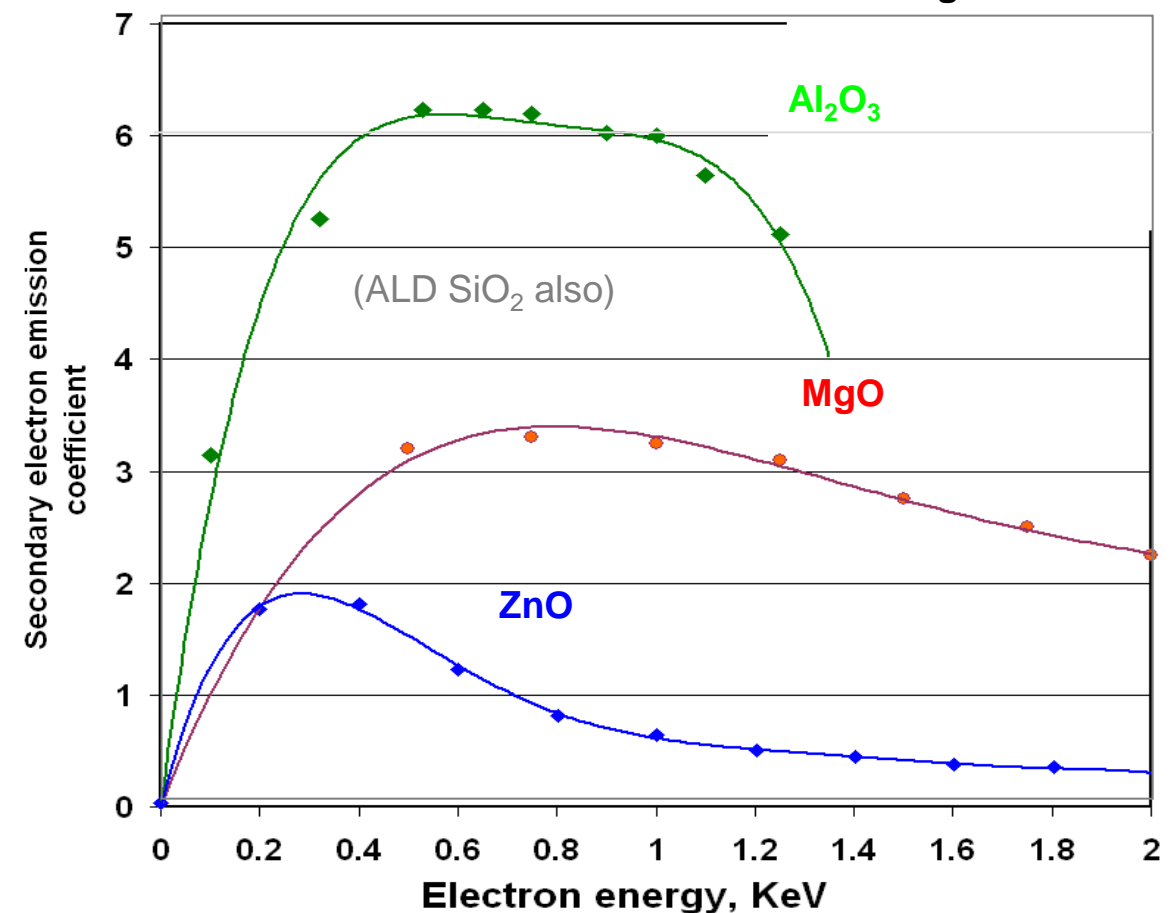
# MCP R&D : Channel Plate Fabrication w/ ALD

## 3. Apply an emissive coating (ALD)

Conventional MCP's:

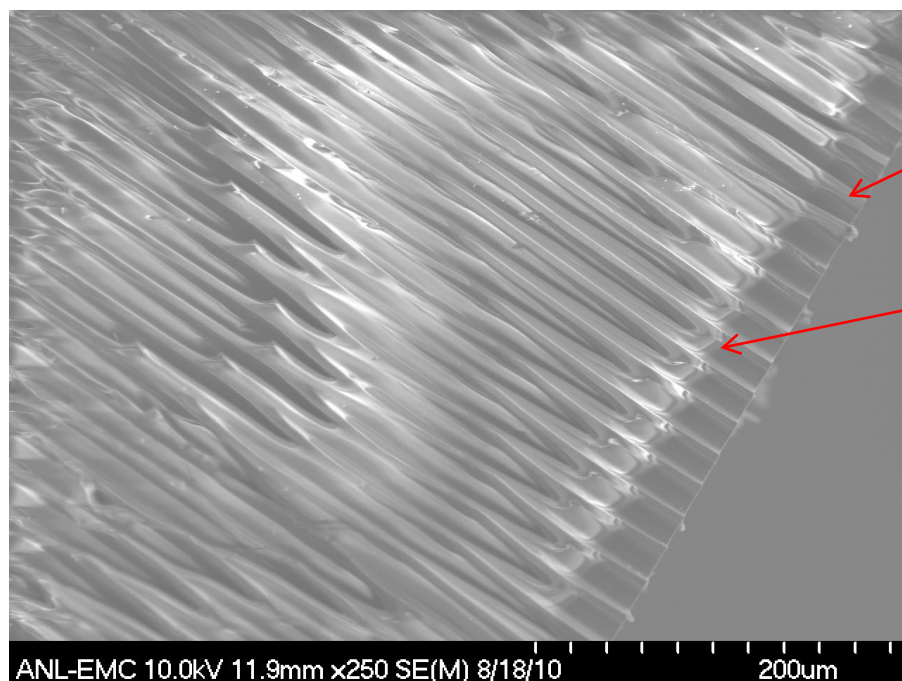
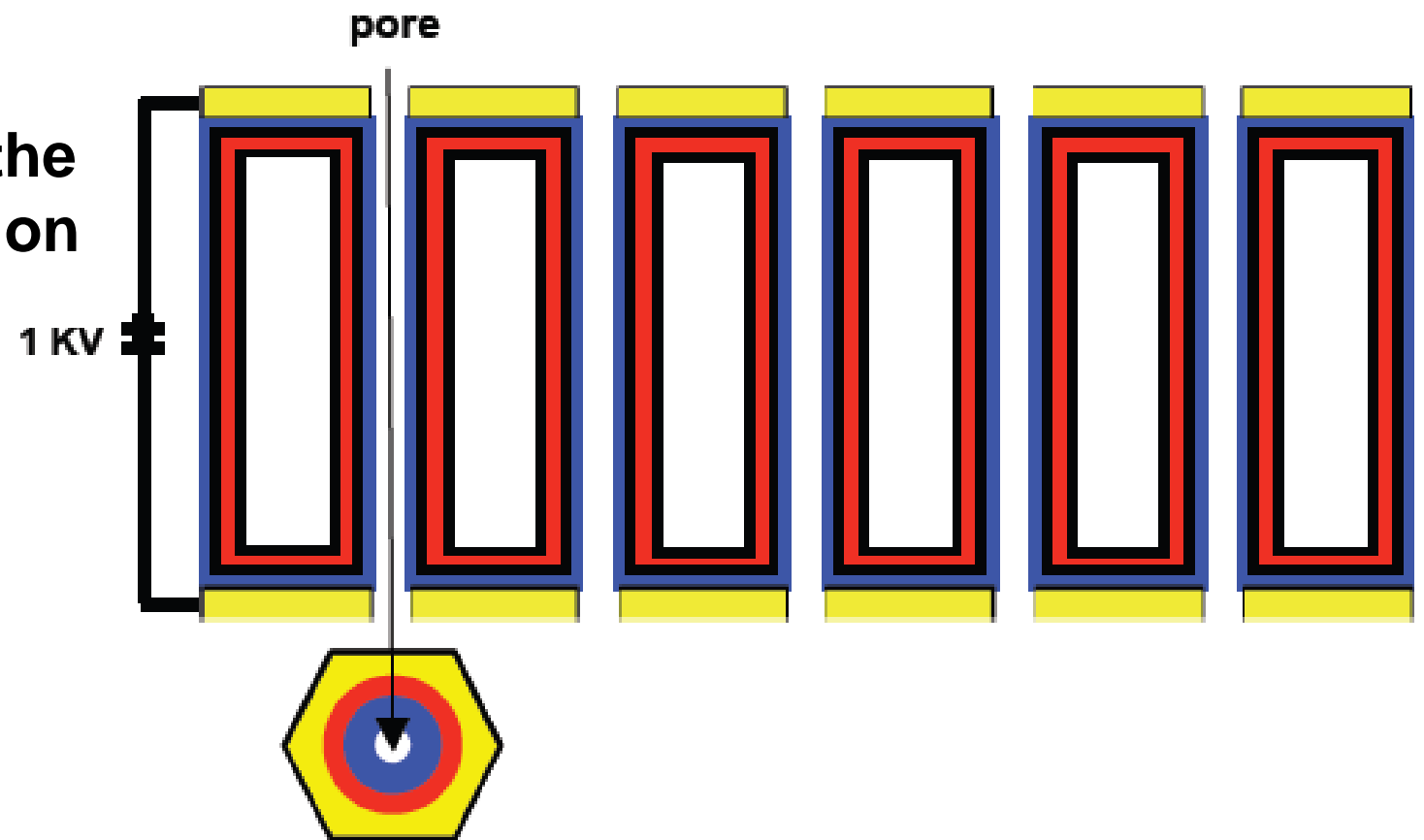
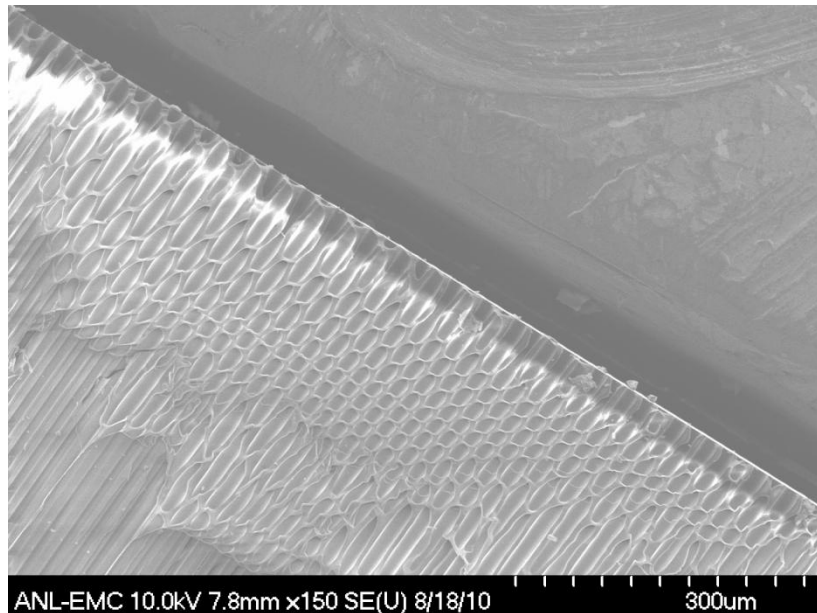


Alternative ALD Coatings:



# MCP R&D : Channel Plate Fabrication w/ ALD

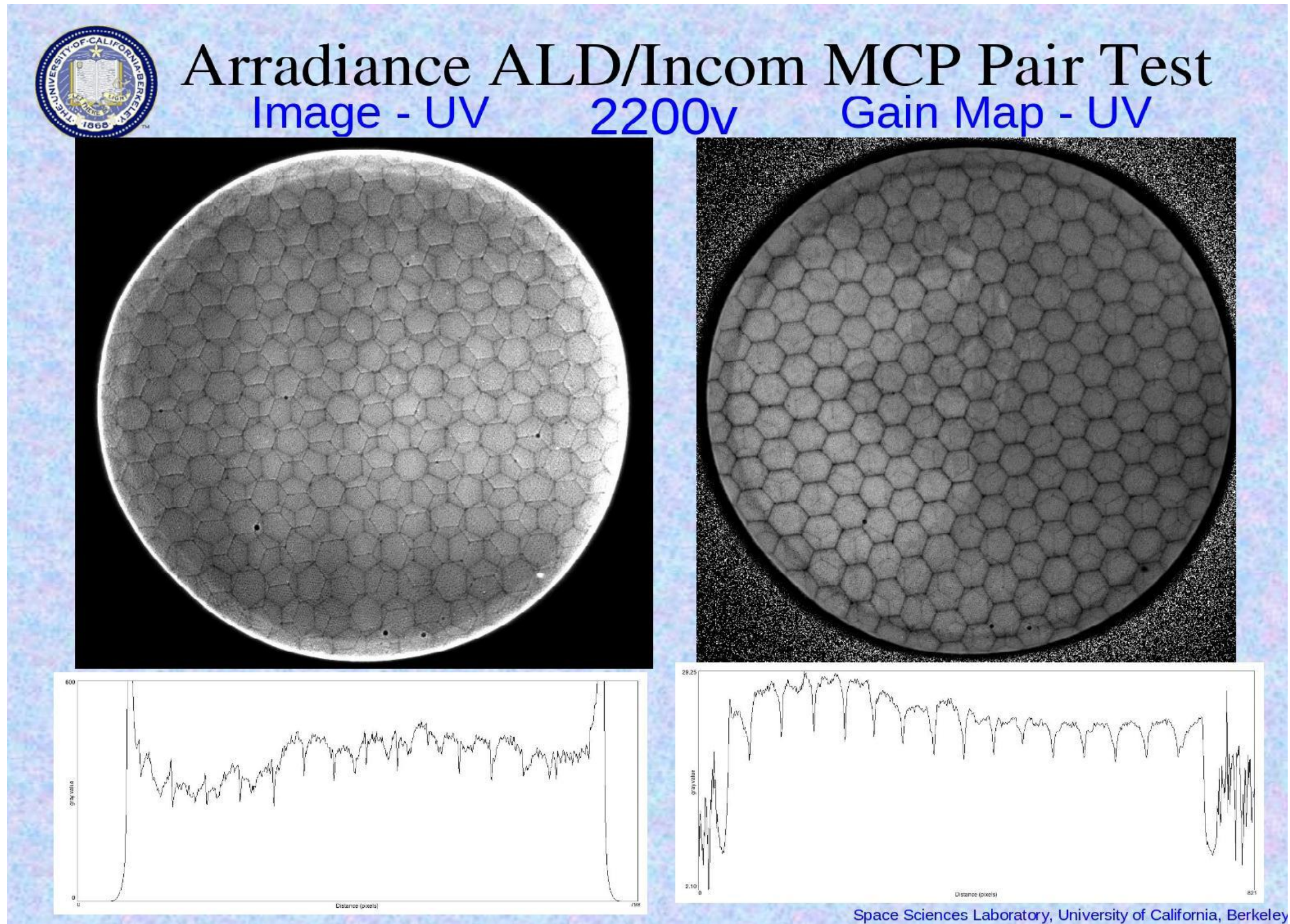
4. Apply a conductive coating to the top and bottom (thermal evaporation or sputtering)



- SEM photos of endspoiling from first use of fixture
- Penetration of electrode into capillary pores is  $\sim 30\mu\text{m}$



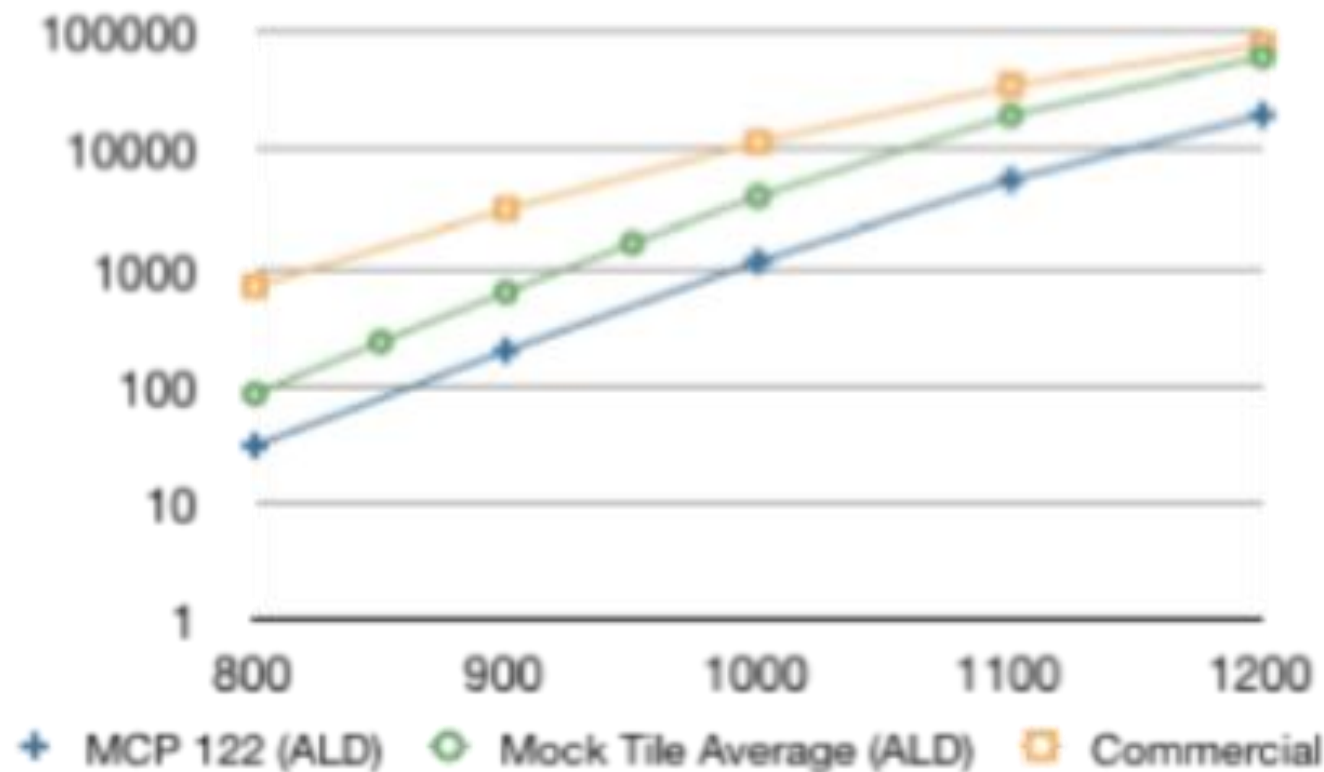
# MCP Development: Testing at SSL



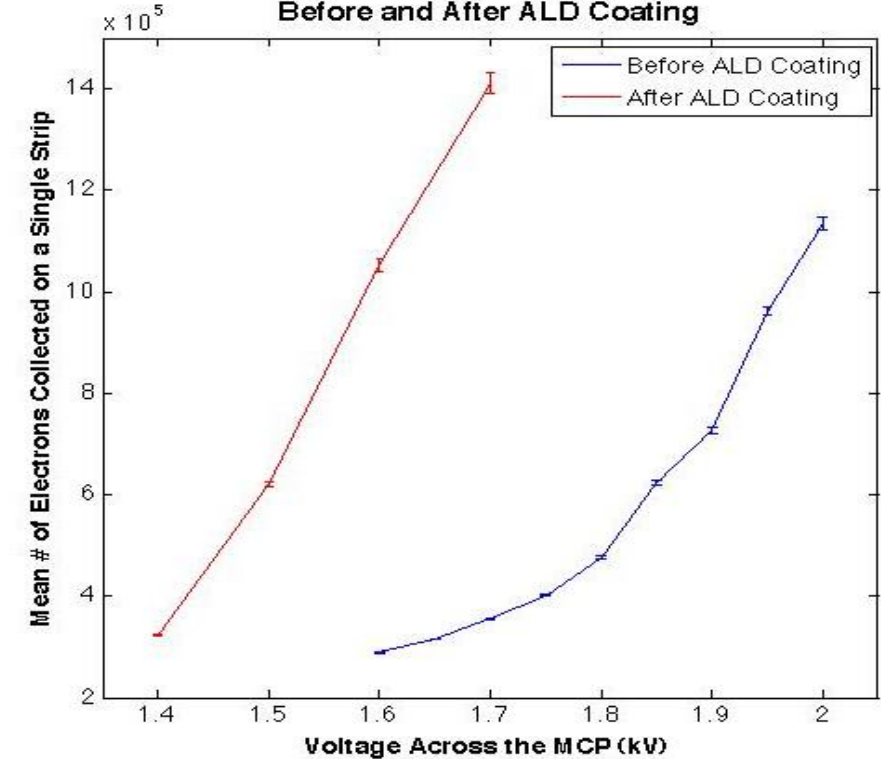


# MCP Development: Testing at ANL

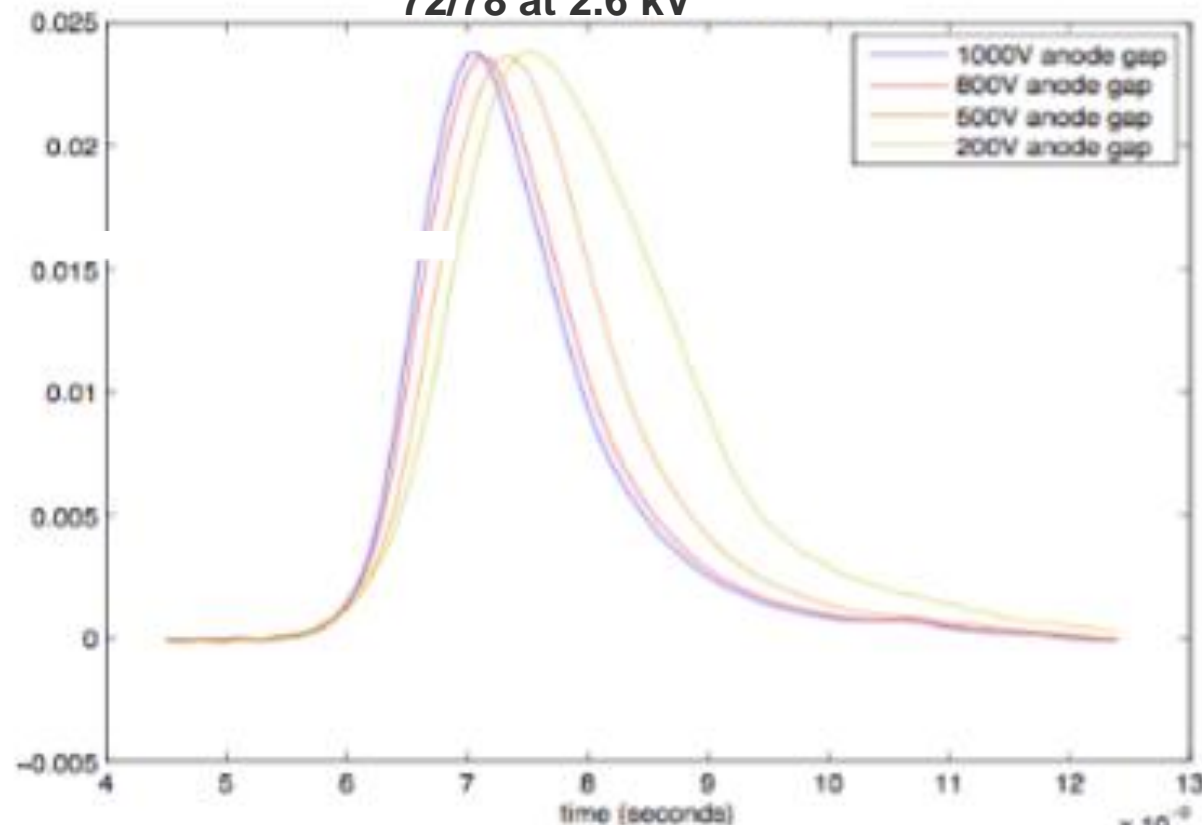
Gain Comparison of ALD-based and Commercial MCPs



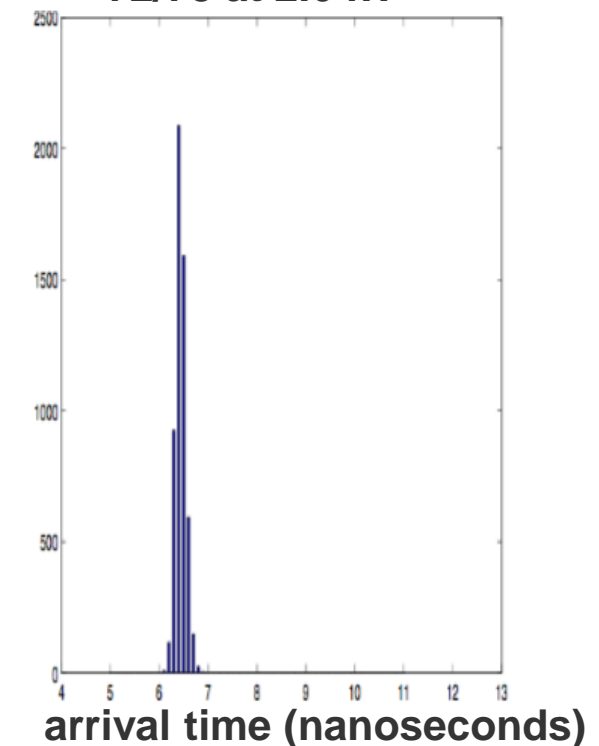
Comparison of MCP Amplification Before and After ALD Coating



Mean Pulse Shape for MCP 72/78 at 2.6 kV

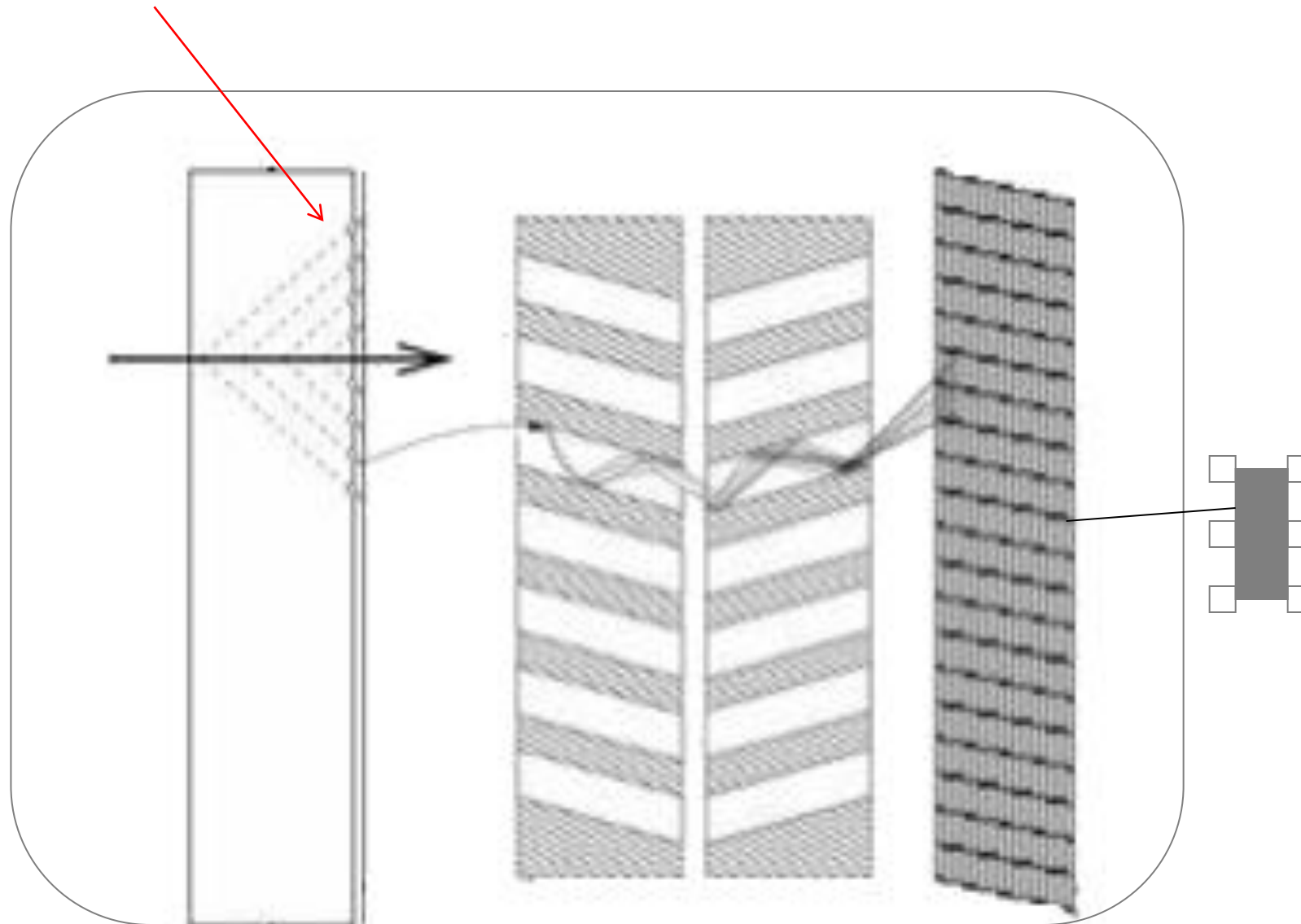


Transit Time Spread for MCP 72/78 at 2.6 kV



arrival time (nanoseconds)

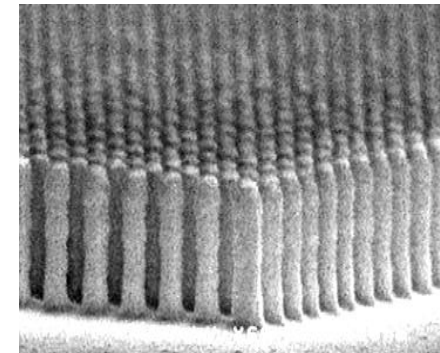
# Photocathodes



# Photocathodes: Three thrusts

Argonne, Space Sciences Lab, UC-Berkeley, Washington Univ.,  
St. Louis, Univ. of Illinois, Chicago

- SSL: R&D focus on scaling up of traditional bi-alkalai to large area
  - Proven history with planacon
- ANL/WashU/UICU: R&D focus on theory inspired design
  - New novel photocathode technologies like nano-structured photocathodes
  - III-V have the potential for high QE, shifting toward the blue and robustness (ie. they age well, high temp)
  - Simulations, testing & characterization
- ANL: R&D focus on design for industrial production of large area photocathodes for a tile factory
  - what does this mean for industry

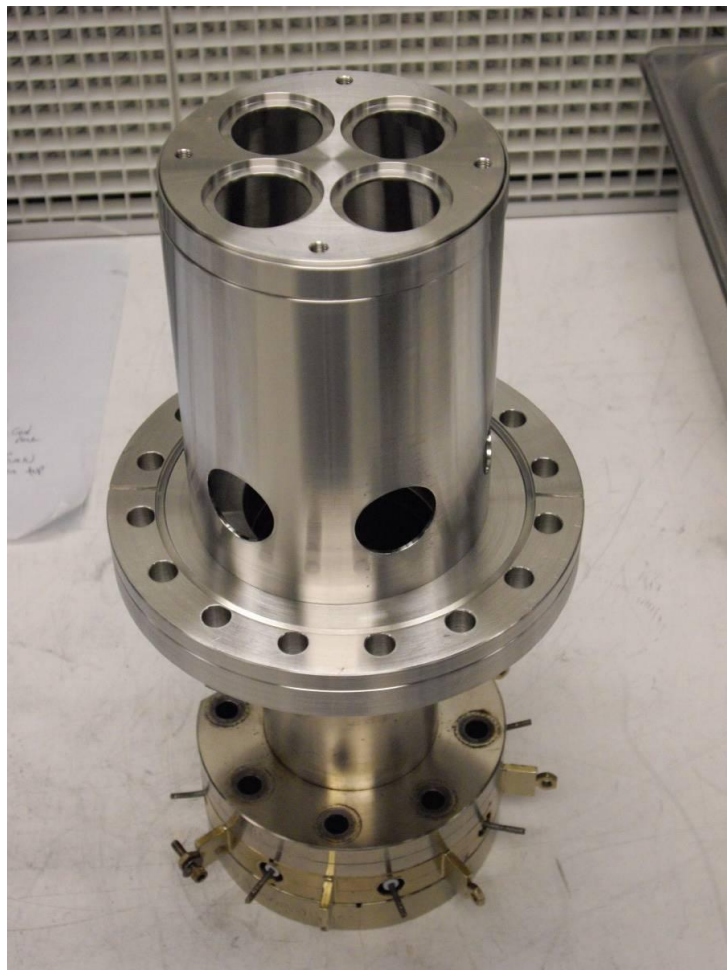


- Nano-structured photocathodes:
  - Reduction of reflection losses (light trap)
  - Heterogeneous structure permits multi-functionality (electrically, optically, electron-emission, "ion-etching resistant")
  - Increased band-gap engineering capabilities



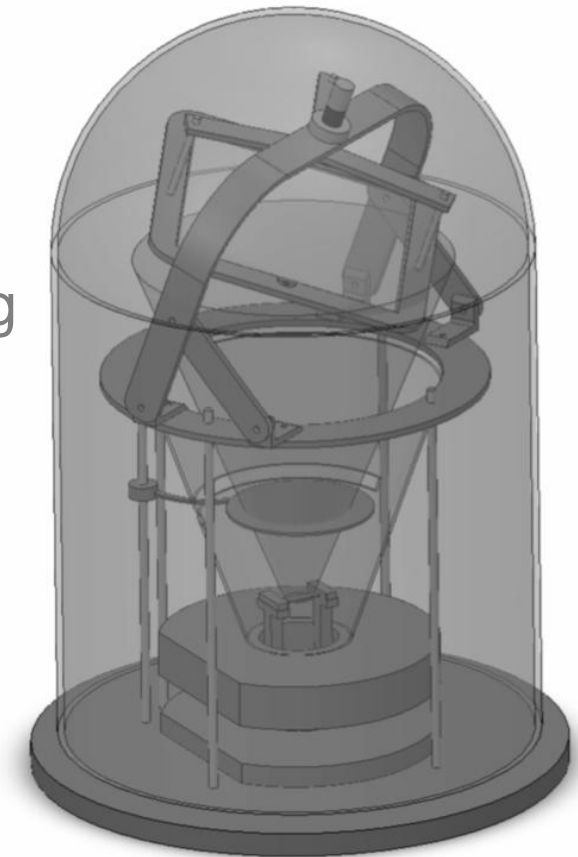
# Photocathode Deposition Development

Work performed by Space Sciences Lab, UC-Berkeley



Small tank for 1.22" test run samples  
Test runs with Fused Silica, Borofloat glass  
ITO & MgO coated ALD layers on glass; scrubbing

Evaporation tooling  
for 8.7" windows

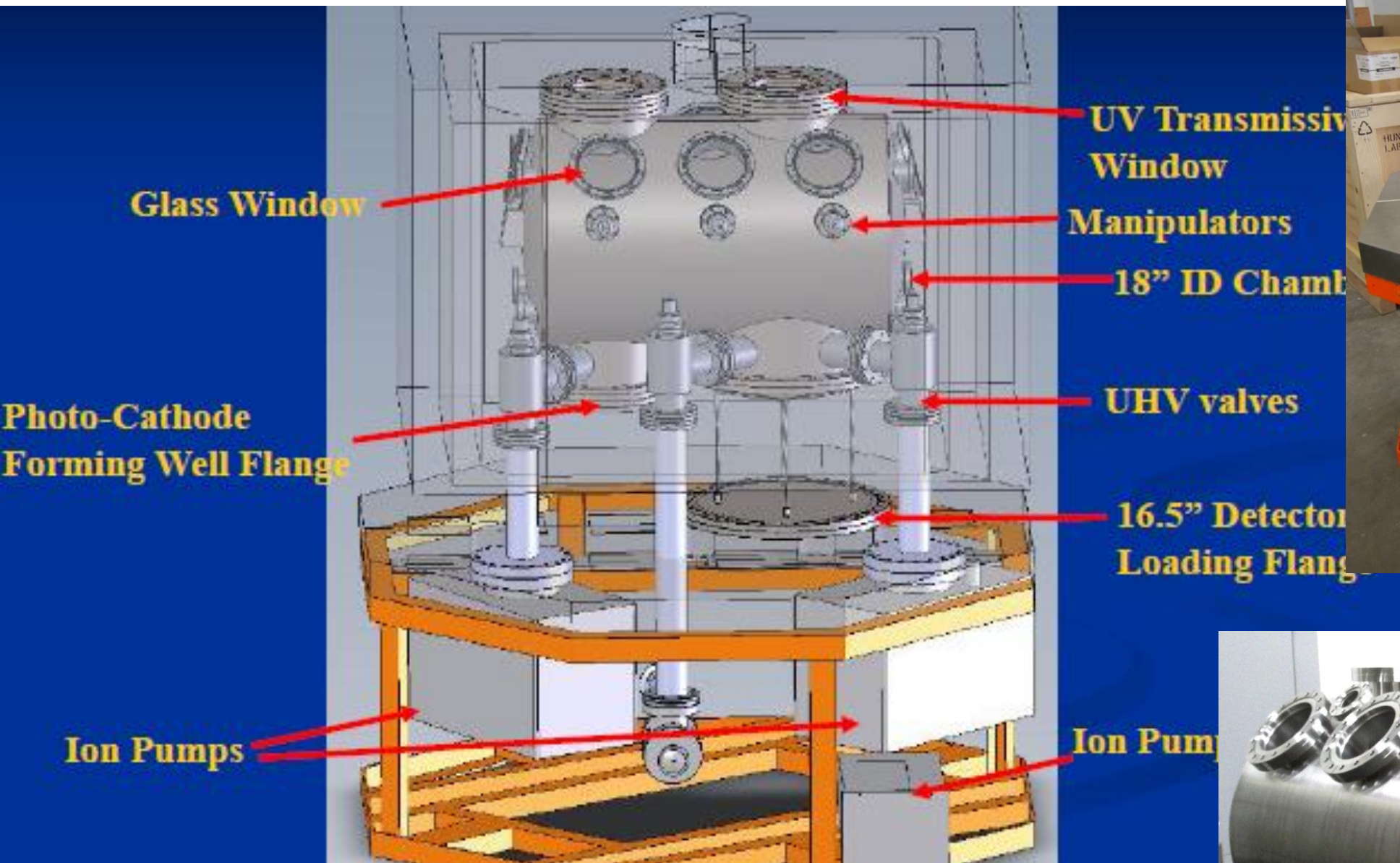


16" tank for full-sized 8.7" windows

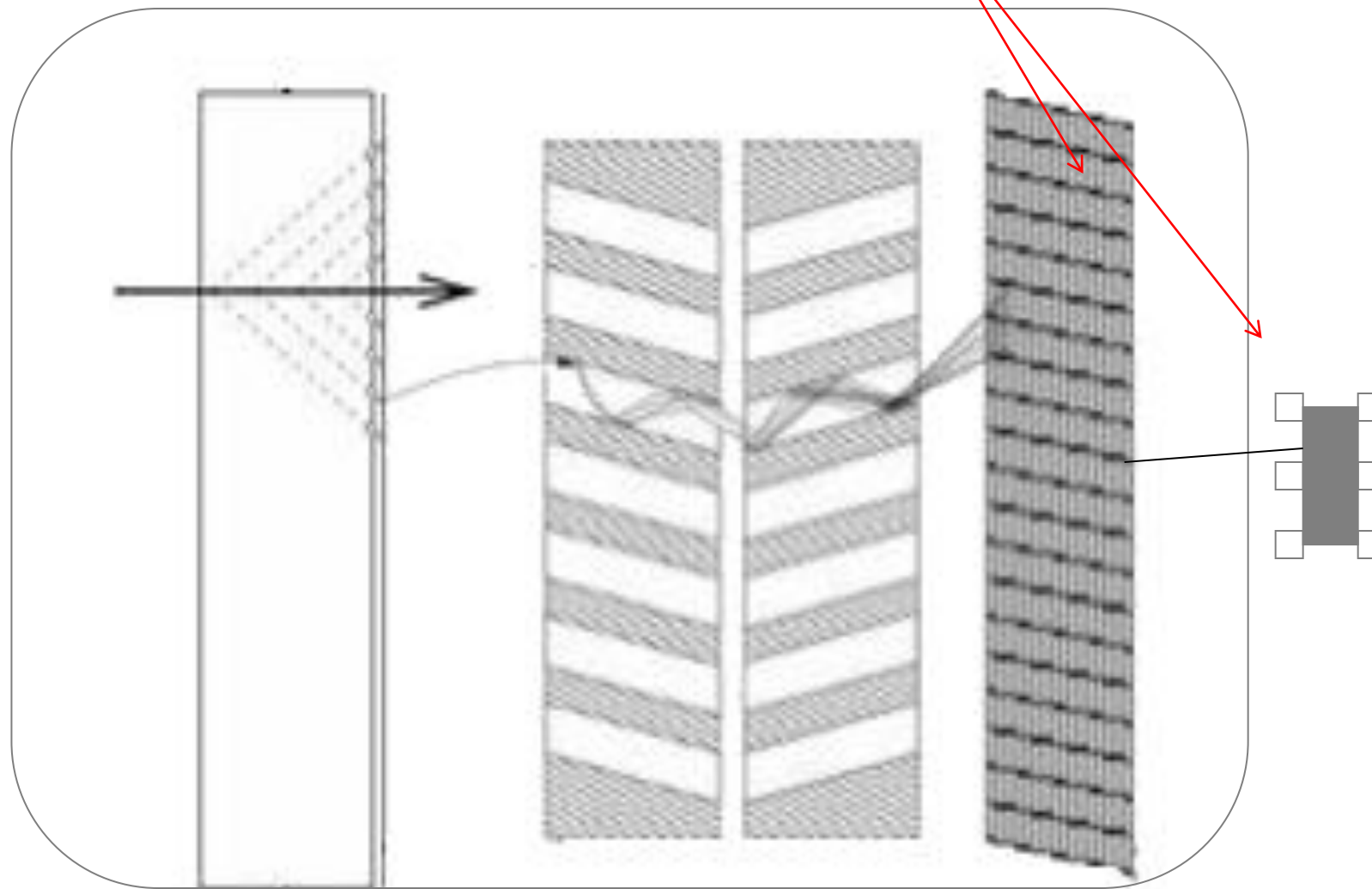




# SSL Large Process Chamber



# Anode and Signal Development





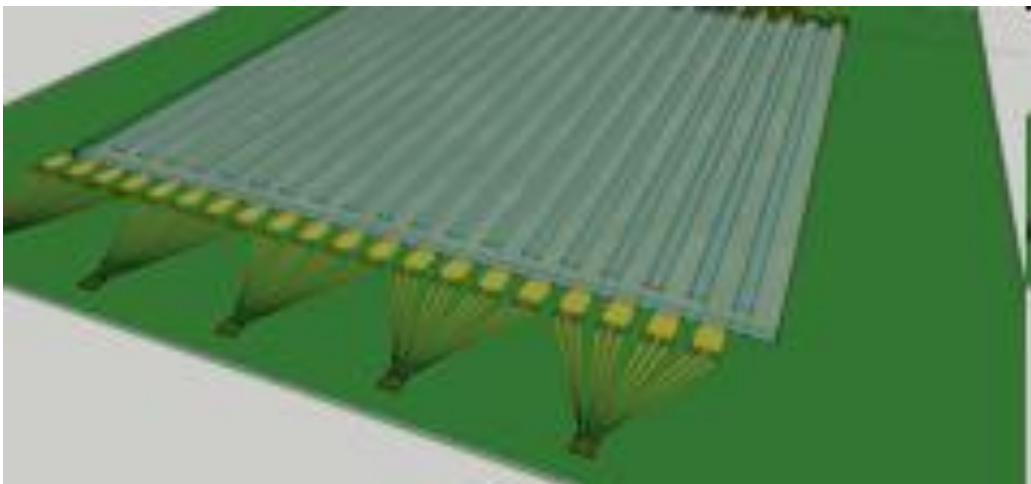
# Anode and Signal Readout

Univ. of Chicago, Univ. of Hawaii

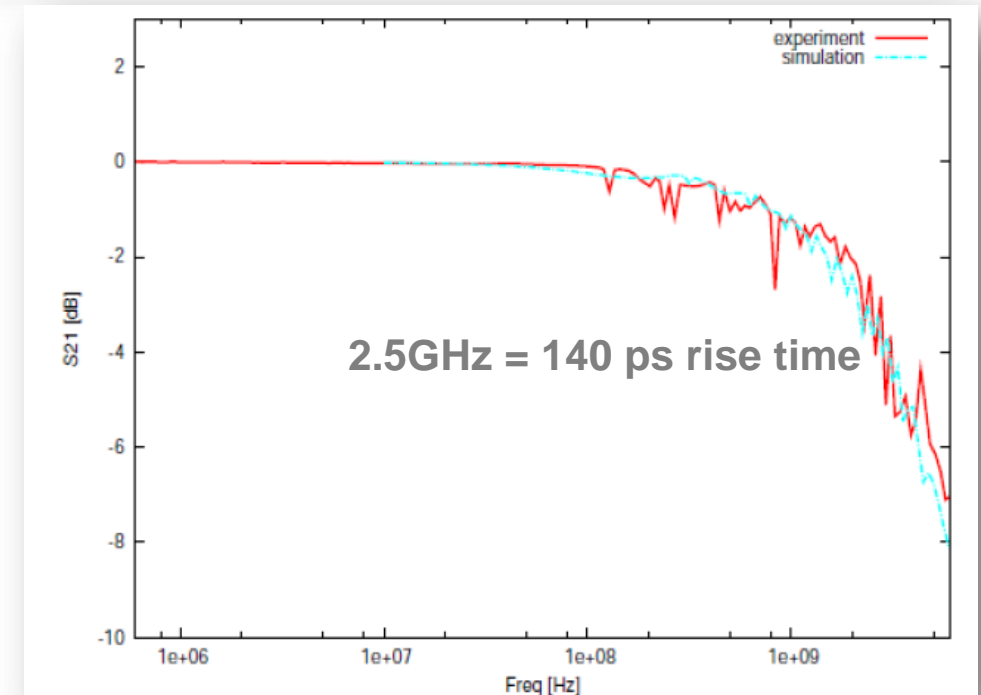
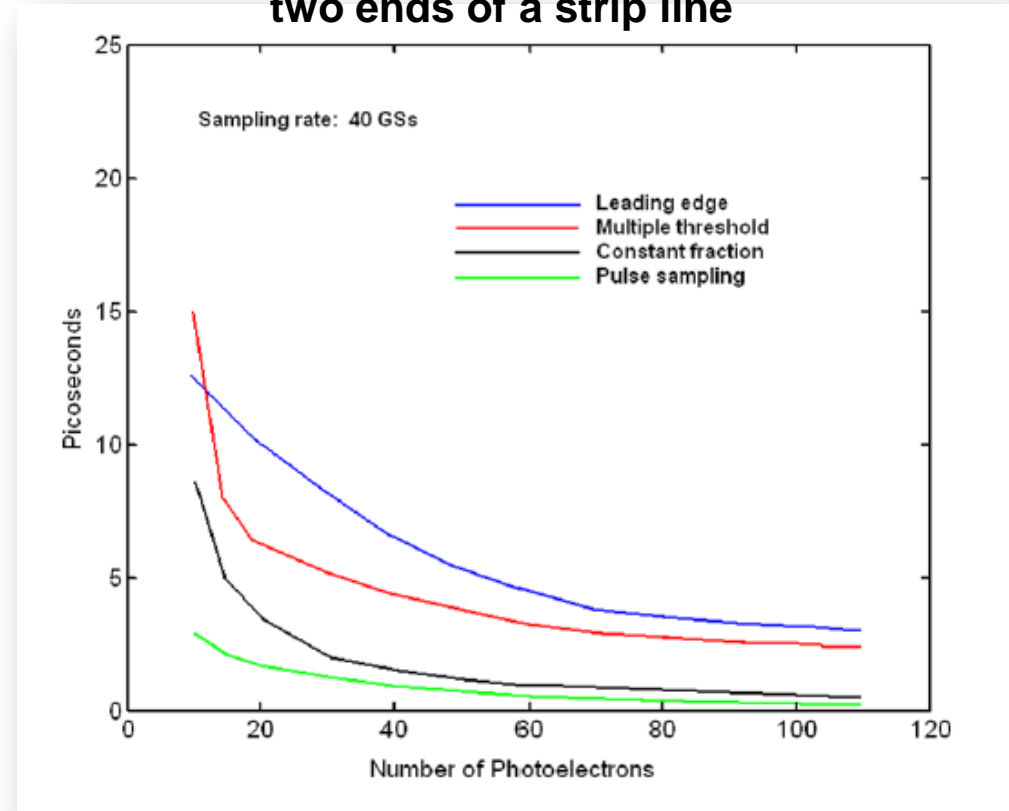
- Resolution depends on & photoelectrons, analog bandwidth, and signal-to-noise.

**Simulations showed “pulse sampling” to give the best results**

- Transmission Line: readout both ends → get position and time
- Cover large areas with much reduced channel count.
- Simulations indicate that these transmission lines could be scalable to large detectors without severe degradation of resolution.

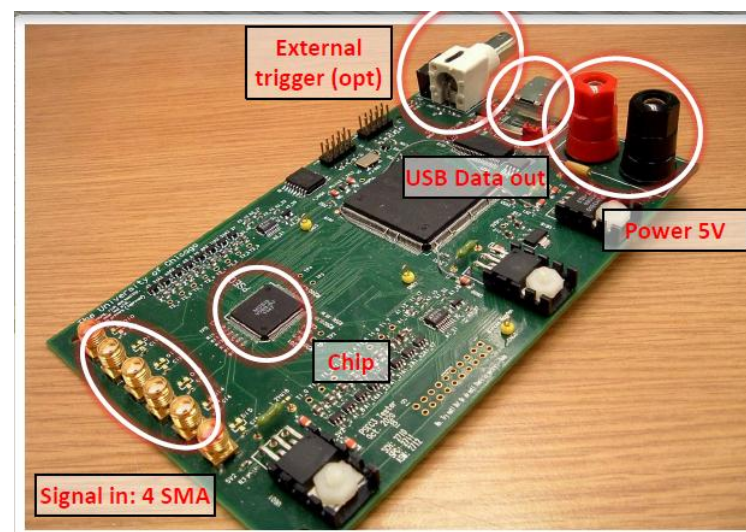
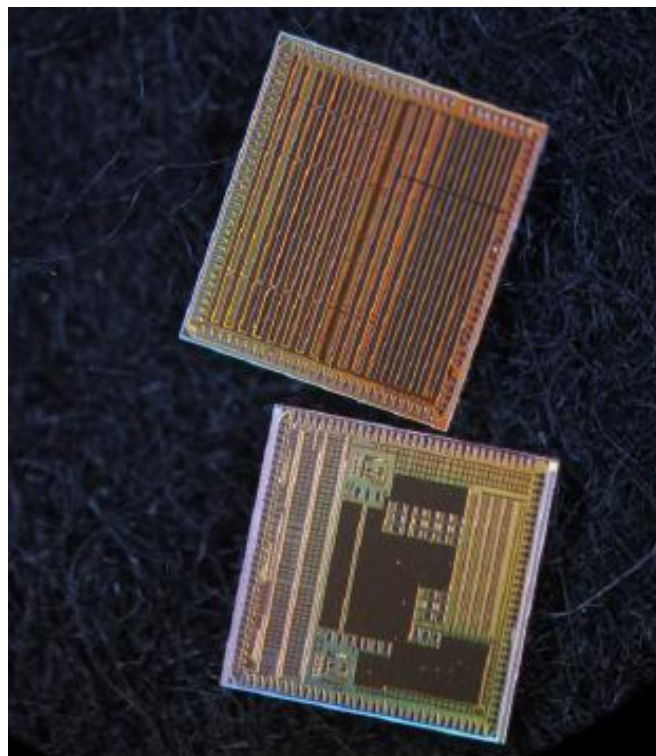
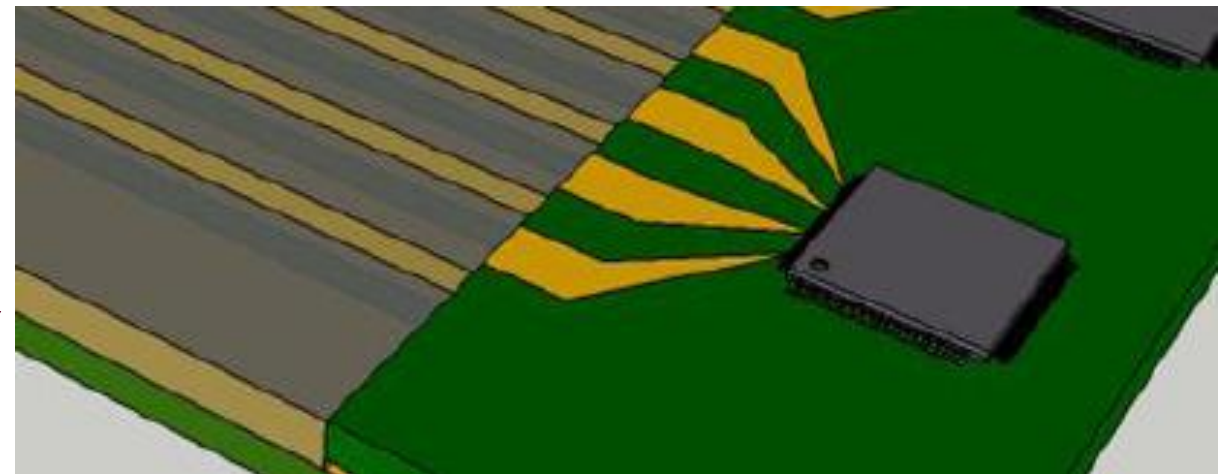


Differential time resolution between two ends of a strip line



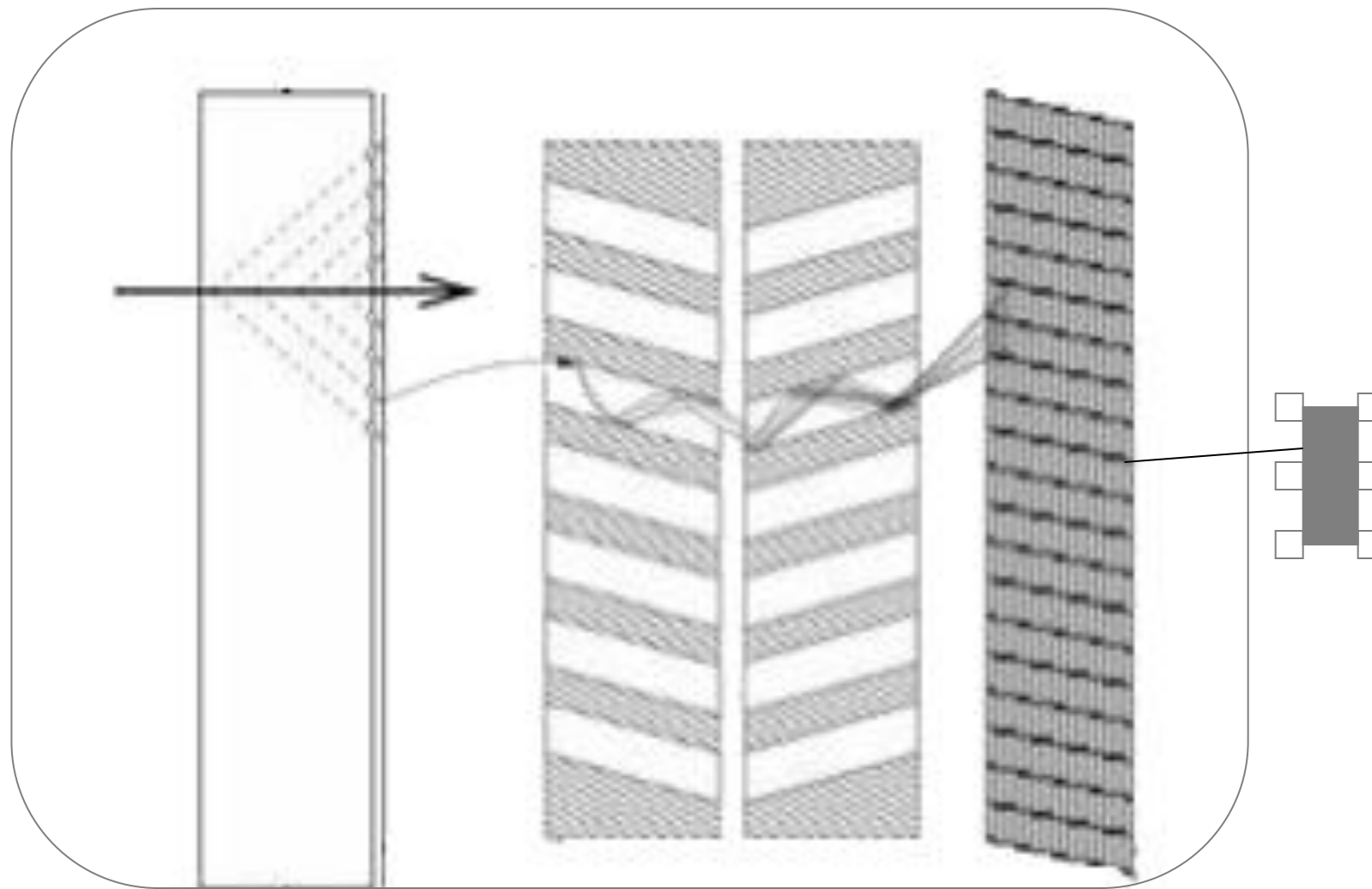
# Anode and Signal Readout: ASIC Sampling Chip

- New 10Gs/s high input bandwidth, 130nm CMOS sampling chip is being developed, "PSEC3"
- Proposed schematic of custom transmission line anode & fast sampling ASIC



Chip characteristics	Value
Technology	IBM CMOS 0.13 $\mu$ m
Sampling frequency	>10Gs/s
Number of channel	4
Number of sampling cells	256
Input bandwidth	>2GHz
Dead time	2 $\mu$ s
Number of bits	8
Power consumption	To be measured

Test board for studying PSEC3

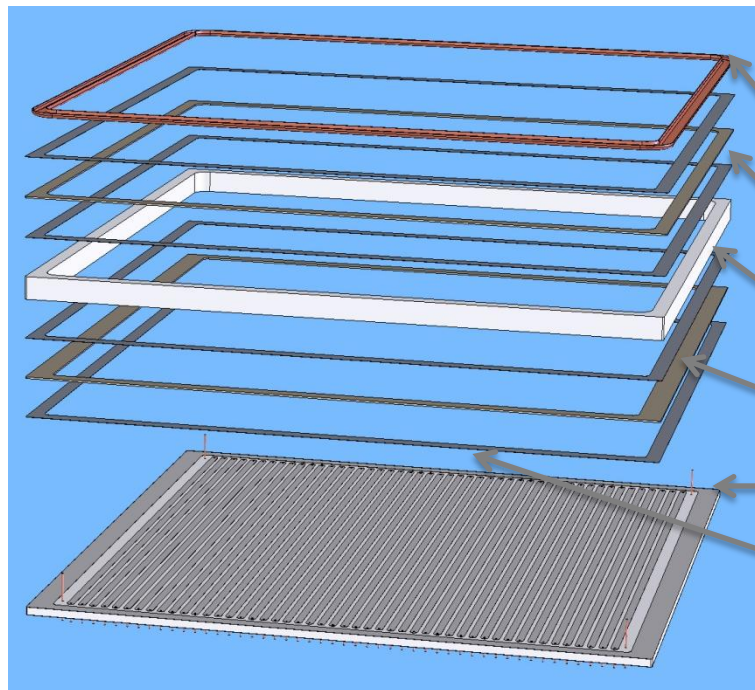




# Mechanical Design: Ceramic

## Space Sciences Lab, UC Berkeley

- Use ceramic assemblies, similar to those used by conventional MCPs.
- Well developed technology, know-how available at SSL.



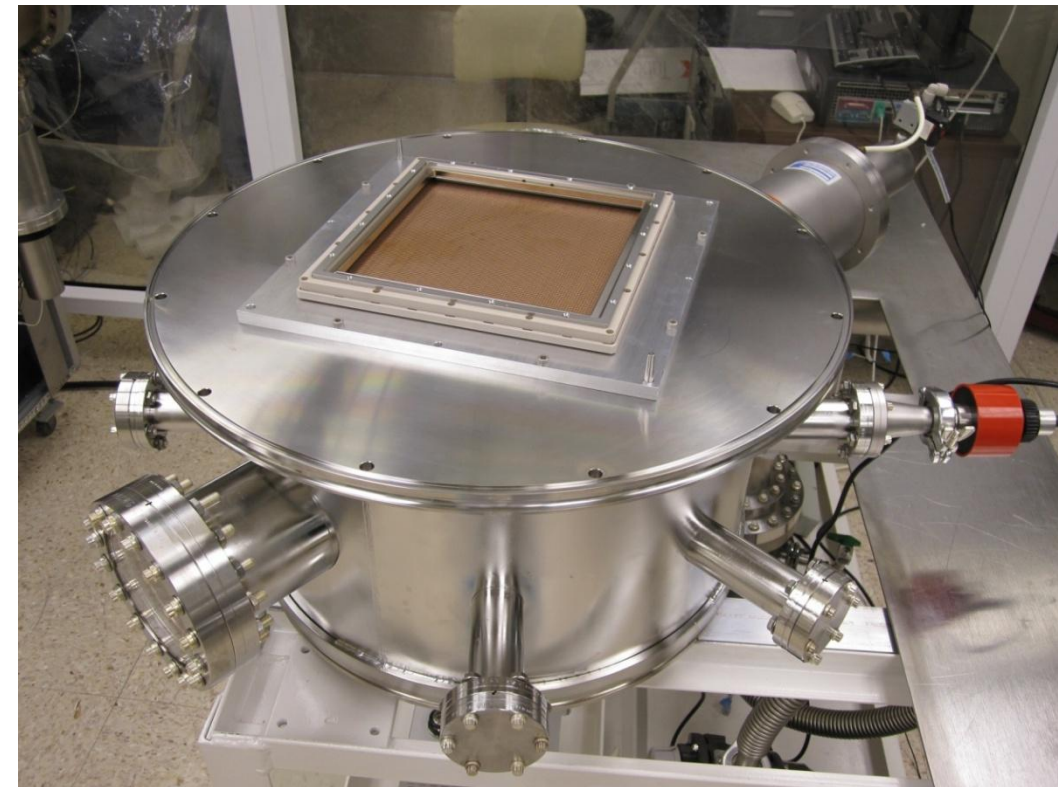
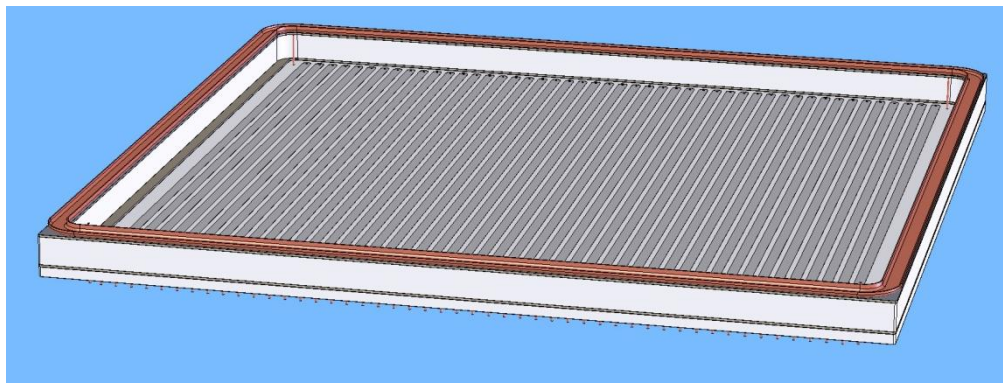
### Single step braze

- Stamped OFHC Cu or Kovar indium well
- Kovar intermediary flange
- Alumina wall
- Kovar getter flange
- HiTemp, CuSil brazed anode

### InCuSil braze alloy (750°C braze)

- Avoids remelt of anode CuSil

### Four braze joints in final assembly



## SSL Vacuum test chamber system for testing 8" MCPs



## SSL Anode Plates





# Mechanical Design: All Glass

Argonne, Univ. of Chicago

## Goals:

- Use inexpensive borosilicate glass for containment vessel
- Avoid use of pins penetrating glass for HV and signal
- Cheap, reliable, reproducible containment vessel fab.
- Demonstrate feasibility with partially active mock-up

## Constraints:

- Support vessel against implosive atmospheric pressure
- Top photocathode window seal at low temp. ( $<120^{\circ}\text{C}$ )
- ~10 yr stability for seal with small leak rate
- Min. handling steps in fabrication
- Avoid particulates in vacuum space
- Materials chemically compatible with alkali metal photocathode

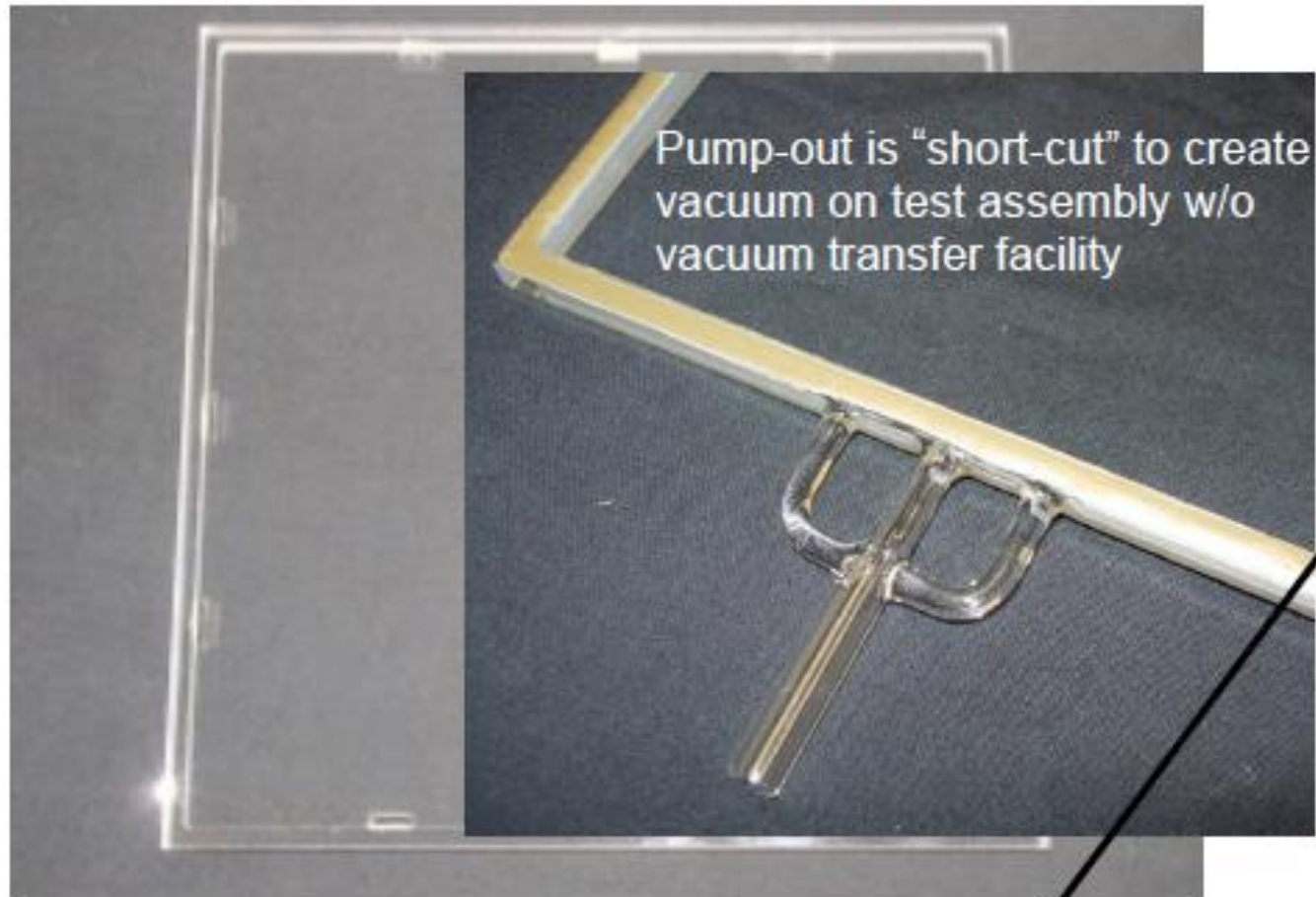


Our first sealed box under pressure.  
It is a 8" square sealed box

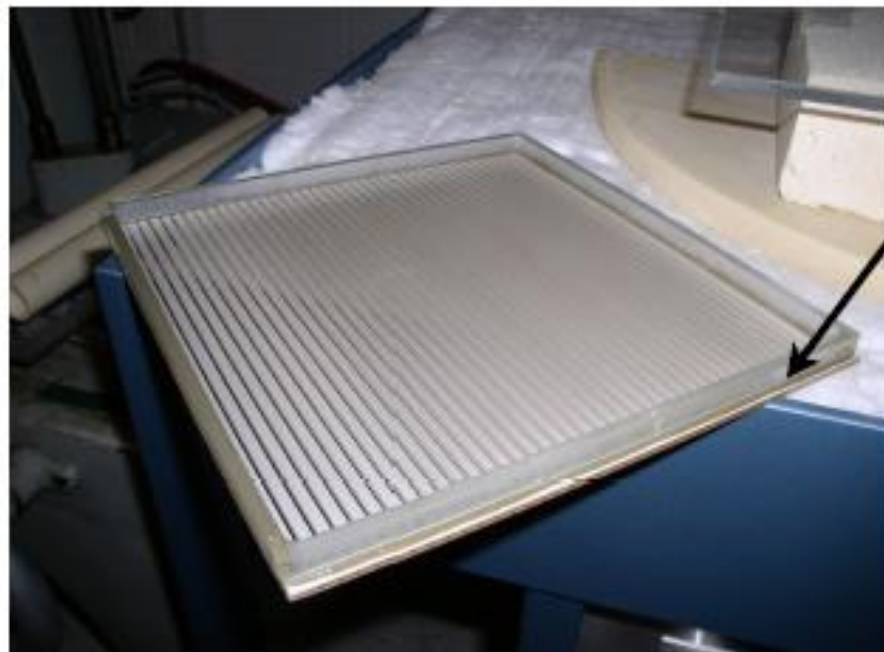




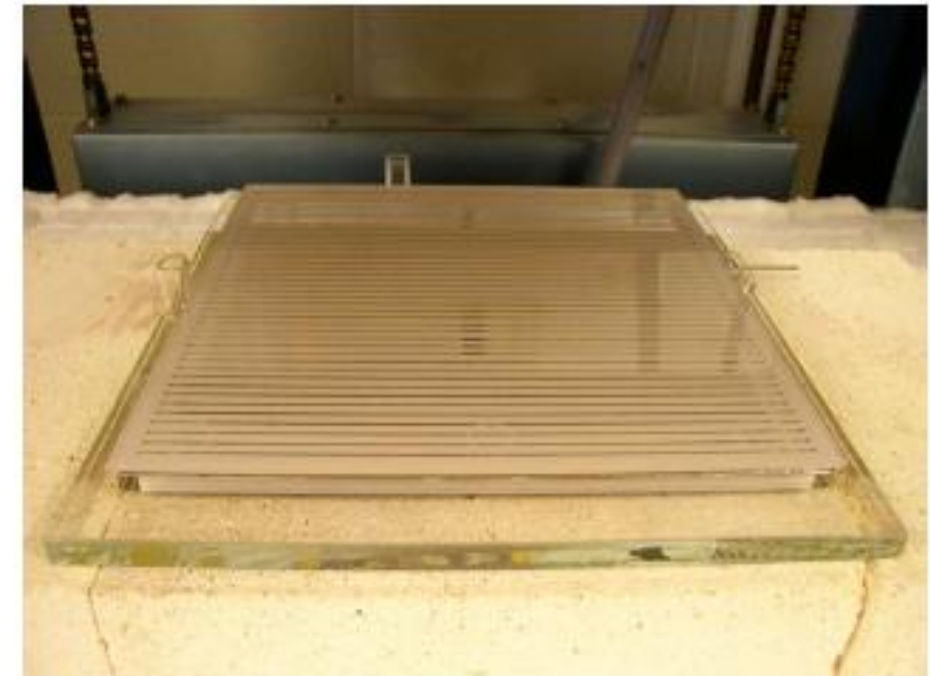
# Tile Base Assembly -- Anode Bottom Plate & Sidewall



- Develop technique to reproducibly bond sidewall to bottom anode plate
  - Center sidewall frame w.r.t. bottom plate; 2 sides flush, equal overhang on anode ground strips
  - Attach getter holder tubes



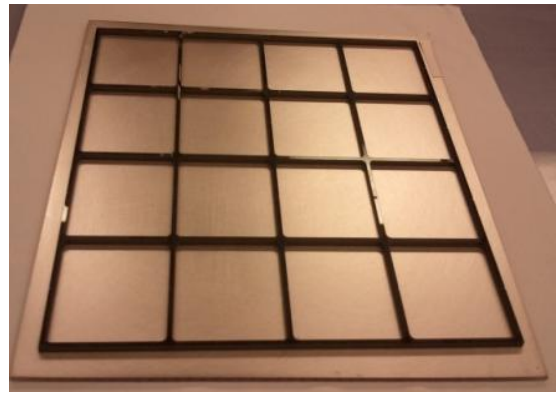
Sidewall bonds on alternating silver strips and bare glass gaps. Extension of strip past sidewall for bridging between tiles & readout connection.



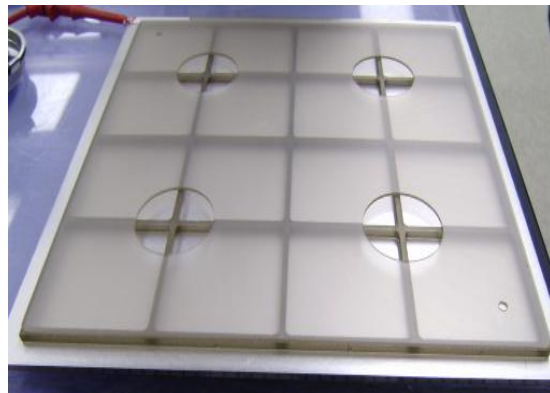
Original steel fritting fixture replaced with much simpler all glass devised by Joe Gregar



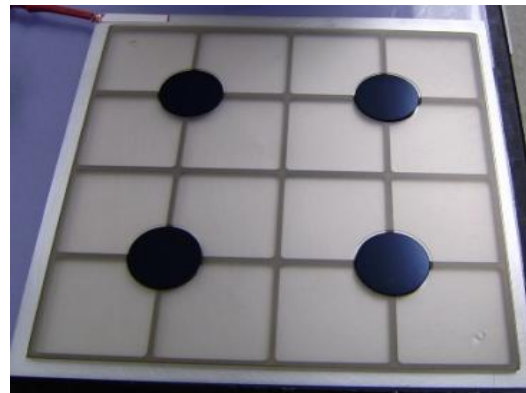
# Construction of first all glass mock tile:



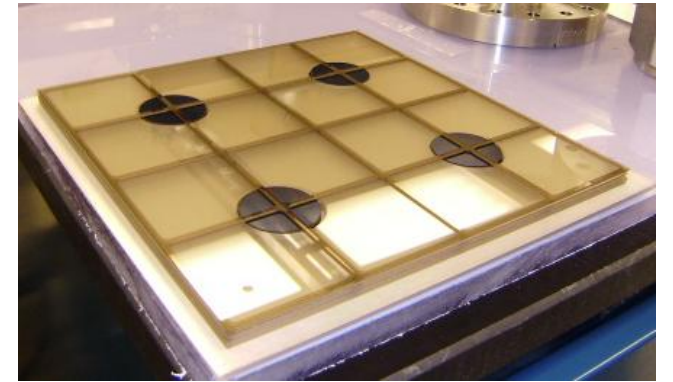
a) 2.97mm bottom Grid Spacer



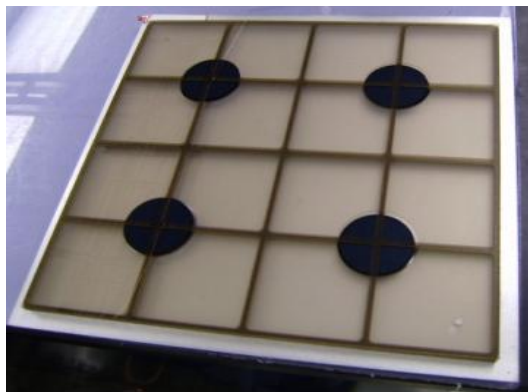
b) add Mock MCP



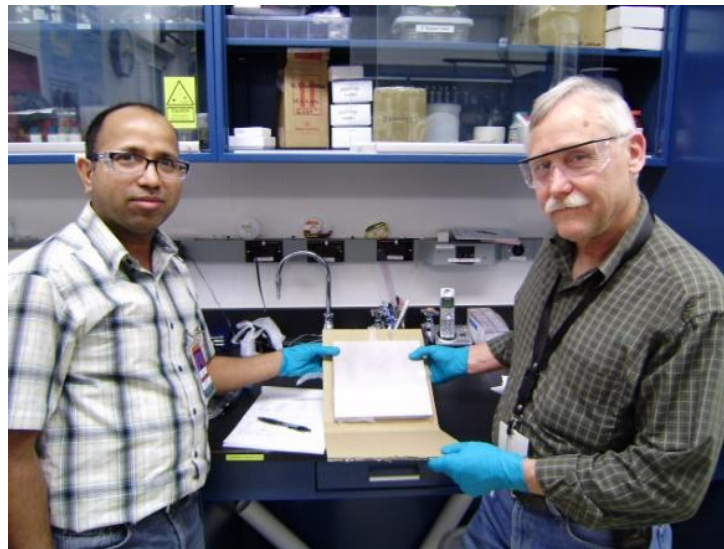
c) add functionalized MCPs



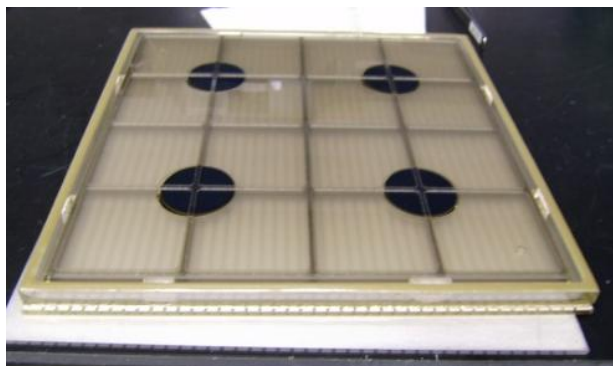
d) add 1.1mm Grid spacer



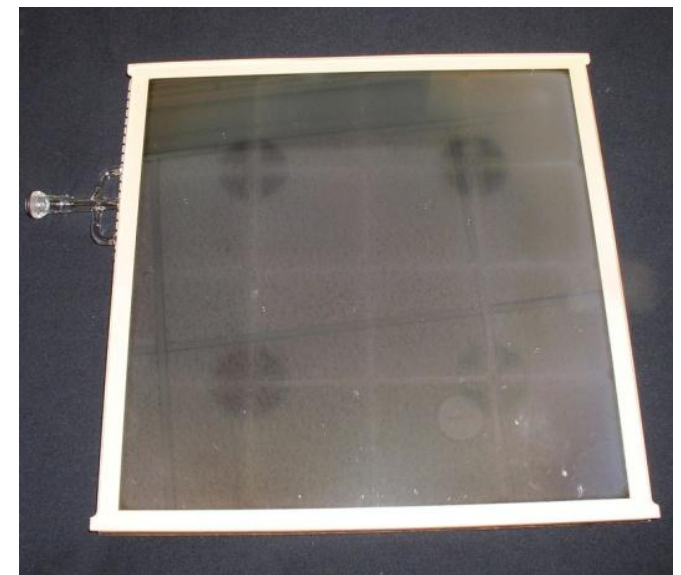
e) Add mock MCPs, 33mm functionalized MCPs & top 1.1mm Grid spacer



g) Anil & Bob Holding mock tile



f) full stack in mock tile



h) Mock tile after sealing & evacuation

# Simulations and Testing

## Microscopic/Materials-Level

## Macroscopic/Device-Level

### Material Science Division, ANL

Constructing dedicated setup for low-energy SEE and PE measurements of ALD materials/photocathodes.

parts-per-trillion capability for characterizing material composition.

### HEP Laser Test Stand, ANL

Fast, low-power laser, with fast scope.

Built to characterize sealed tube detectors, and front-end electronics.

Highly Automated

### Berkeley SSL

Decades of experience.

Wide array of equipment for testing individual and pairs of channel plates.

Infrastructure to produce and characterize a variety of conventional photocathodes.

### Advanced Photon Source, ANL

Fast femto-second laser, variety of optical resources, and fast-electronics expertise.

Study MCP-photocathode-stripline systems close to device-level. Timing characteristics amplification etc.



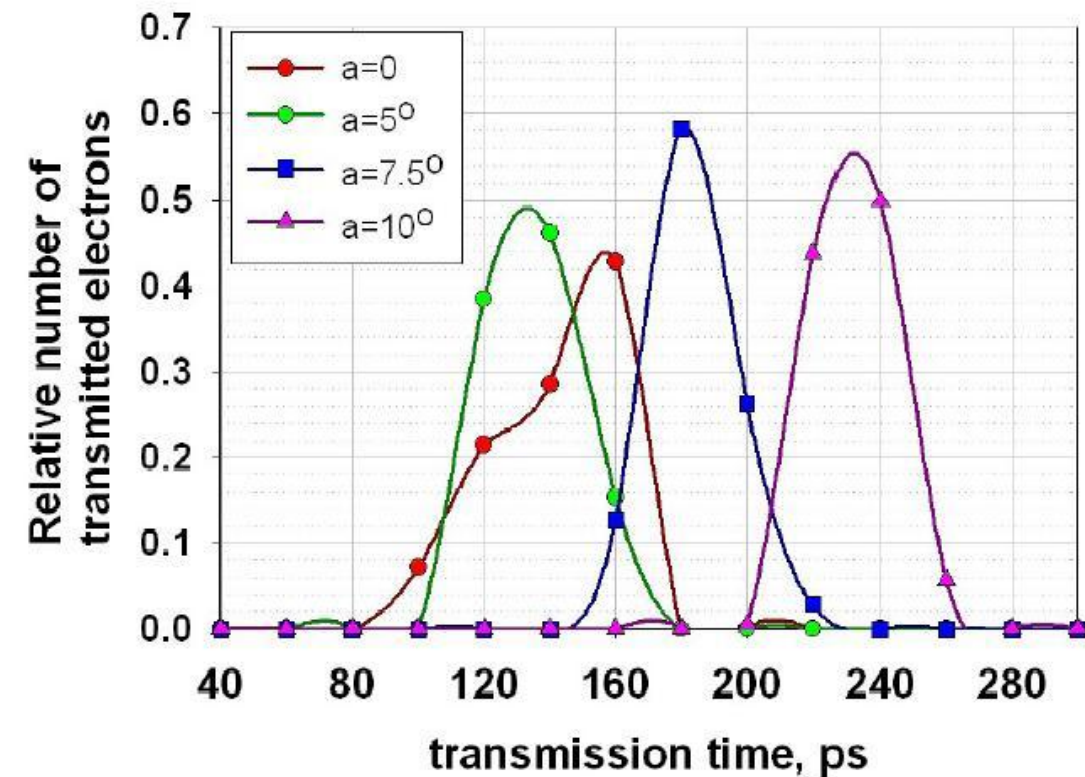


## Transit Time Spread (TTS)

- Working to develop a first-principles model to predict MCP behavior, at device-level, based on microscopic parameters.
- Will use these models to understand and optimize our MCP designs.

## TTS

Comparison of TTS for direct and tilted channels



## Trajectories

MCP size:

Diameter = 25  $\mu\text{m}$   
Length = 1000  $\mu\text{m}$   
Aspect ratio 40

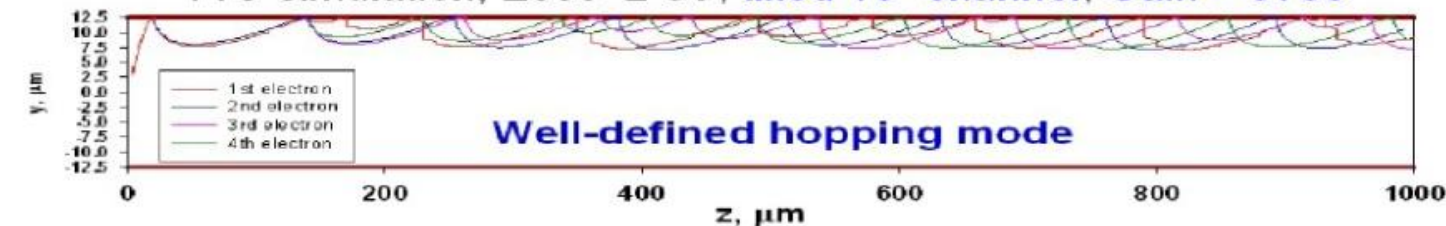
TTS simulation,  $E_{\text{sec}}=2$  eV, direct channel, Gain = 14



TTS simulation,  $E_{\text{sec}}=2$  eV, tilted  $7.5^\circ$ , Gain = 143



TTS simulation,  $E_{\text{sec}}=2$  eV, tilted  $10^\circ$  channel, Gain = 3730



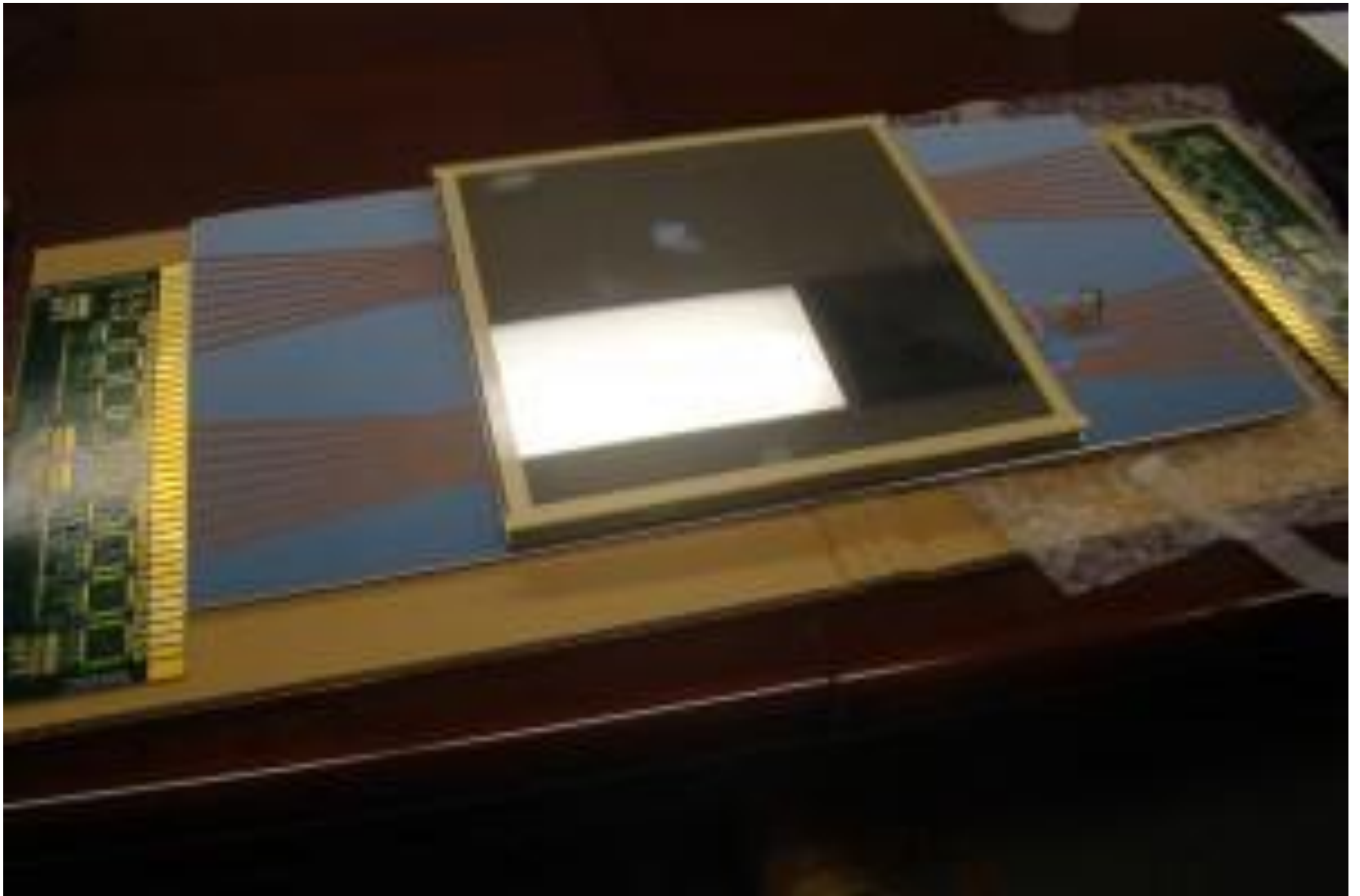


# Conclusion

- Large Area Picosecond Photodetector Development collaboration is on track to deliver a working prototype by the end of year 3 (summer 2012)
- Atomic Layer Deposition coatings of 33mm glass capillary disks are producing gain  $>10^6$  for MCP pair; Are in the process of scaling up to 8" ALD
- Have developed 3 ALD resistive + 2 ALD emissive chemistries
- Mature mechanical designs for hermetically sealed tube
  - Proven design in ceramic by SSL
  - Well-advanced inexpensive glass design -- first hermetic box completed
- Moving to reliable and reproducible fabrication of sealed tubes in quantity
- Designing a tile production facility at Argonne
  - Lab space for tile facility is being developed
  - Layout design of labs for wet chemistry and vacuum handling underway



# Anode and Signal Readout: First Mock Tile



# ▸ Backup





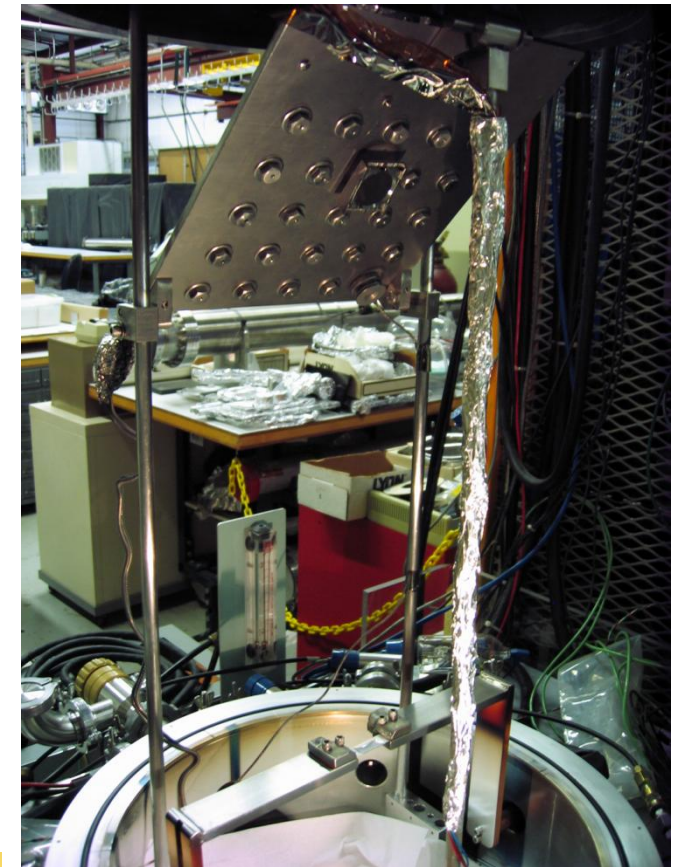
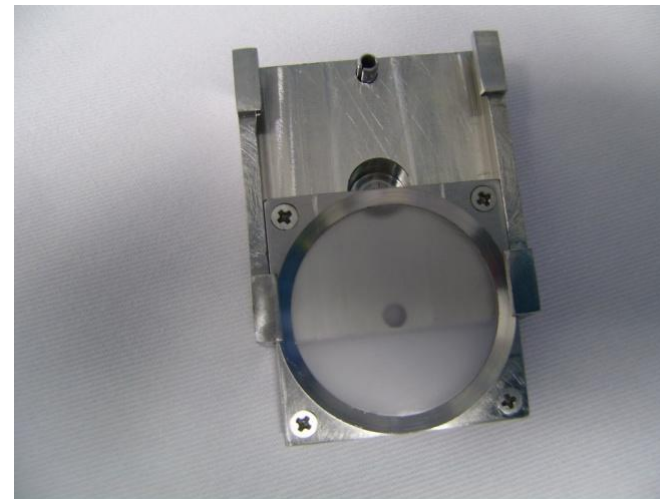
# MCP Development: Electrode Evaporation onto MCPs - Endspoiling

Fermilab and Space Sciences Laboratory, Berkeley, UC

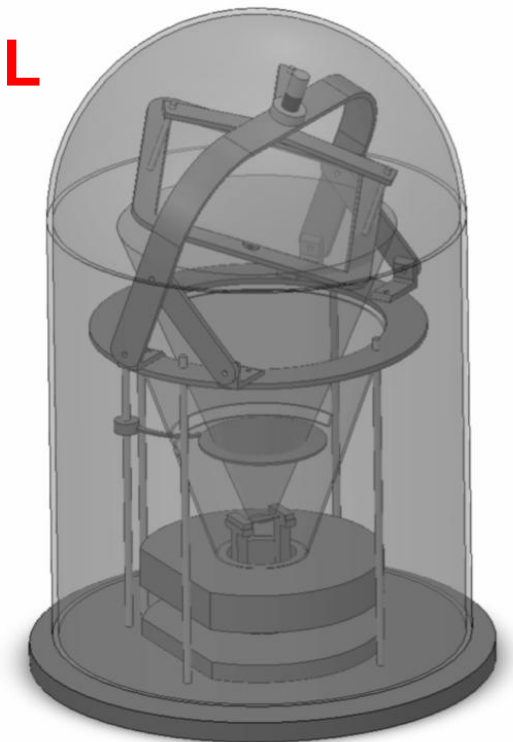
**FNAL**

- Metallization for electrical contact applied to bare glass capillary before ALD
- Nichrome evaporation performed at Fermilab Thin Film Facility and as SSL
- FNAL Fixture must rotate MCP about  $8^\circ$  bias of pores
- Penetration of electrode into pores is 1 diameter, i.e.  $20\mu\text{m}$  (endspoiling)

**SSL current Bell jar setup for fixturing 33mm sample evaporations and cartoon of modifications to accommodate 8" tiles**



**SSL**





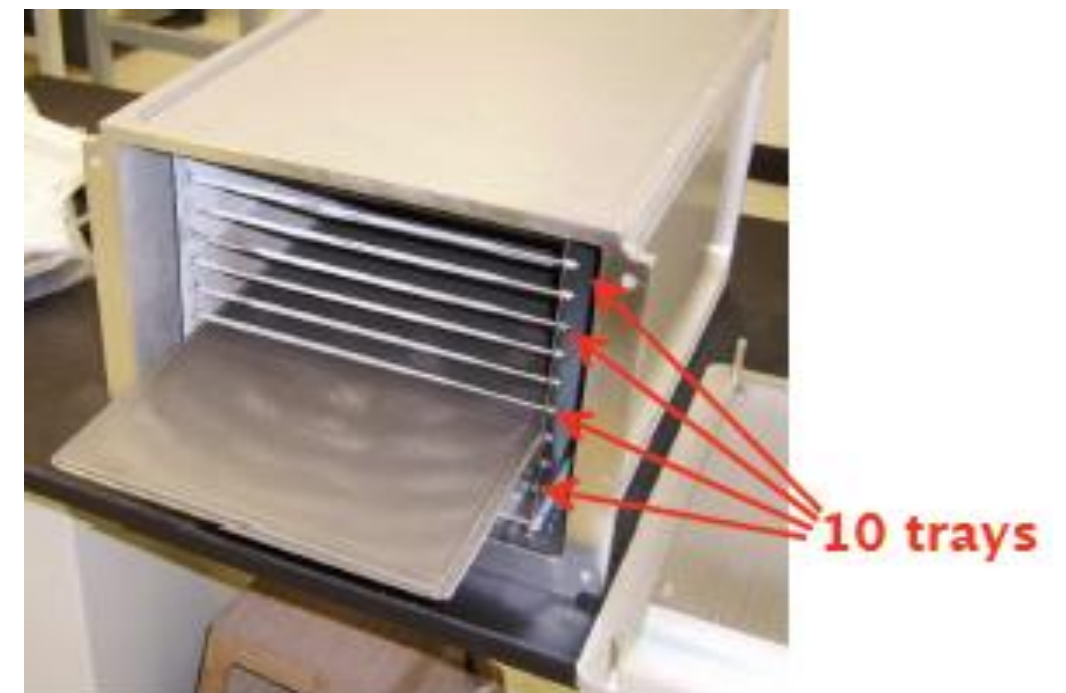
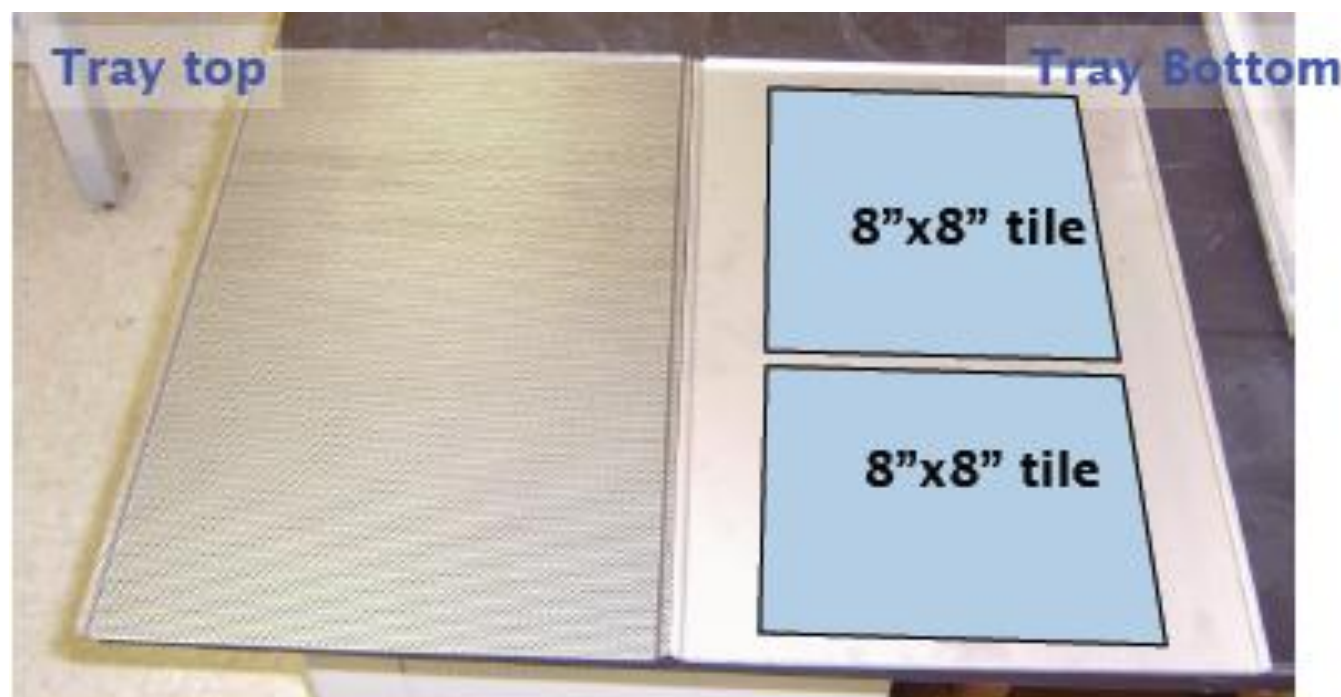
# MCP Development: Scale-up of ALD Processing

## Studying ALD on Large Surface Areas

- 33mm disk surface area is  $0.13\text{m}^2$
- 8" x 8" surface area is  $6.4\text{m}^2$
- 20 MCPs area is  $129\text{m}^2$



**New Beneq Reactor**





# New Photocathode Lab at Argonne w/Burle Equipment



## New Burle Equip.

- Just sitting up equipment
- First photocathodes w/QE>15%
- Plan to use this eqpt for mock tile assembly scaleup



Photocathode Lab Plan View

